

OPAx355 200MHz CMOSオペアンプ、シャットダウン付き

1 特長

- ユニティ・ゲイン帯域幅: 450MHz
- 広い帯域幅: 200MHz GBW
- 低ノイズ: 5.8nV/√Hz
- 非常に優れたビデオ性能
 - 差動ゲイン: 0.02%
 - 差動位相: 0.05°
 - 0.1dBのゲイン・フラットネス: 75MHz
- 入力範囲にグランドを含む
- レール・ツー・レール出力(100mV以内)
- 低い入力バイアス電流: 3pA
- 低いシャットダウン時電流: 3.4μA
- イネーブル/ディセーブル時間: 100ns/30ns
- サーマル・シャットダウン
- 単一電源動作電圧範囲: 2.5V~5.5V
- MicroSIZEパッケージ

2 アプリケーション

- ビデオ処理
- 超音波
- 光ネットワーク、調節可能なレーザー
- フォトダイオード・トランスインピーダンス・アンプ
- アクティブ・フィルタ
- 高速積分器
- A/Dコンバータ(ADC)入力バッファ
- D/Aコンバータ(DAC)出力アンプ
- バーコード・スキャナ
- 通信

3 概要

OPA355シリーズの高速、電圧帰還型CMOSオペアンプは、広い帯域幅を必要とするビデオおよびその他のアプリケーション用に設計されています。OPA355シリーズはユニティ・ゲイン安定で、大きな出力電流を駆動できます。また、OPAx355シリーズはデジタル・シャットダウン(イネーブル)機能を備えています。この機能により、アイドル時の省電力を実現し、出力をハイ・インピーダンス状態にして出力多重化をサポートします。差動ゲインは0.02%、差動位相は0.05°です。静止電流はチャンネルごとに8.3mAです。

OPAx355シリーズは、最低2.5V (±1.25V)、最高5.5V (±2.75V)のシングル電源またはデュアル電源で動作するよう最適化されています。同相入力範囲はグランドより100mV下、V+より1.5V上までです。出力スイングはレールから100mV以内で、広いダイナミック・レンジに対応しています。

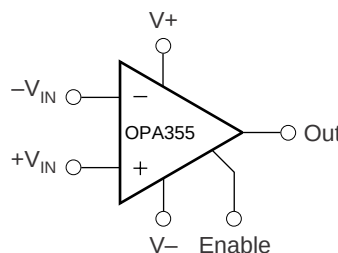
OPAx355シリーズはシングル(SOT-23-6およびSO-8)、デュアル(VSSOP-10)、およびトリプル(TSSOP-14およびSO-14)バージョンで供給されます。マルチチャネル・バージョンは、完全に独立した回路により、クロストークを最小化し、干渉の発生を防止しています。いずれのパッケージも、-40°C~+125°Cで動作が規定されています。

製品情報⁽¹⁾

型番	パッケージ	本体サイズ(公称)
OPA355	SOIC (8)	4.90mm×3.91mm
	SOT-23 (6)	2.90mm×1.60mm
OPA2355	VSSOP (10)	3.00mm×3.00mm
OPA3355	SOIC (14)	8.65mm×3.91mm
	TSSOP (14)	5.00mm×4.40mm

(1) 提供されているすべてのパッケージについては、データシートの末尾にある注文情報を参照してください。

概略回路図



目次

1	特長	1	8.3	Feature Description	16
2	アプリケーション	1	8.4	Device Functional Modes	17
3	概要	1	9	Application and Implementation	18
4	改訂履歴	2	9.1	Application Information	18
5	Device Comparison Table	3	9.2	Typical Applications	18
6	Pin Configuration and Functions	4	9.3	Video	22
7	Specifications	7	9.4	Wideband Video Multiplexing	23
7.1	Absolute Maximum Ratings	7	10	Power Supply Recommendations	25
7.2	ESD Ratings	7	11	Layout	25
7.3	Recommended Operating Conditions	7	11.1	Layout Guidelines	25
7.4	Thermal Information: OPA355	8	11.2	Layout Example	25
7.5	Thermal Information: OPA2355	8	12	デバイスおよびドキュメントのサポート	26
7.6	Thermal Information: OPA3355	8	12.1	関連リンク	26
7.7	Electrical Characteristics: $V_S = 2.7\text{ V to }5.5\text{ V}$ (Single-Supply)	9	12.2	ドキュメントの更新通知を受け取る方法	26
7.8	Typical Characteristics	11	12.3	コミュニティ・リソース	26
8	Detailed Description	16	12.4	商標	26
8.1	Overview	16	12.5	静電気放電に関する注意事項	26
8.2	Functional Block Diagram	16	12.6	Glossary	26
			13	メカニカル、パッケージ、および注文情報	27

4 改訂履歴

資料番号末尾の英字は改訂を表しています。その改訂履歴は英語版に準じています。

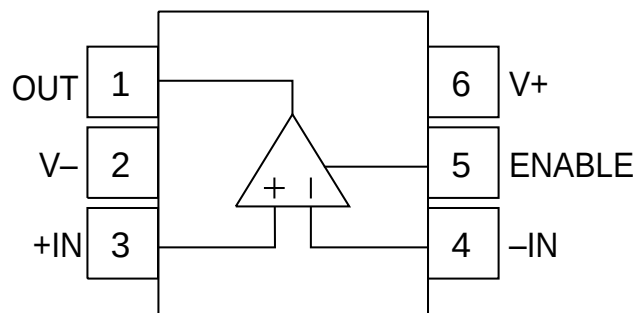
Revision D (January 2004) から Revision E に変更	Page
• 最新のTISドキュメントおよび翻訳基準に合わせてデータシートを更新	1
• 「概要」セクションのピン・タイプの誤字をMSOPからVSSOPに変更	1
• 製品情報の表 追加	1
• Deleted the <i>Absolute Maximum Ratings</i> table note: Input terminals are diode-clamped to the power-supply rails. Input signals that can swing more than 0.5 V beyond the supply rails should be current limited to 10 mA or less.	7
• Added <i>ESD Ratings</i> table	7
• Added <i>Recommended Operating Conditions</i> table	7
• Added <i>Thermal Information</i> tables	8
• Changed pin type typo from MSOP to VSSOP in <i>Electrical Characteristics</i> section	10
• 削除 the test conditions statement from <i>Typical Characteristics</i> graphs and moved the conditions to tablenotes below the graphs	11
• 追加 <i>Detailed Description</i> section	16
• 追加 <i>Functional Block Diagram</i> graphic	16
• 削除 <i>Input and ESD Protection</i> section	16
• 追加 <i>Application and Implementation</i> section	18
• 削除 <i>Internal ESD Protection</i> application	18
• 追加 <i>Power Supply Recommendations</i> section	25
• 追加 <i>Layout Guidelines</i> section	25

5 Device Comparison Table

OPAx355 RELATED PRODUCTS	FEATURES
OPA356	200-MHz, Rail-to-Rail Output, CMOS, No Shutdown
OPAx350	38-MHz, Rail-to-Rail Input and Output, CMOS
OPAx631	75-MHz, Rail-to-Rail Output
OPAx634	150-MHz, Rail-to-Rail Output
THS412x	Differential Input and Output, 3.3-V Supply

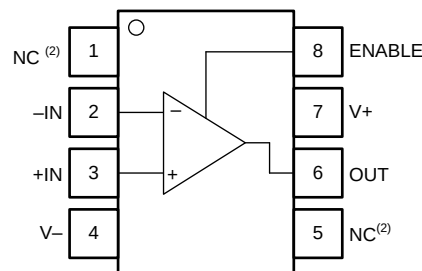
6 Pin Configuration and Functions

**OPA355 DBV Package
6-Pin SOT-23
Top View**



- (1) Pin 1 of the SOT-23-6 is determined by orienting the package marking as indicated in the diagram.

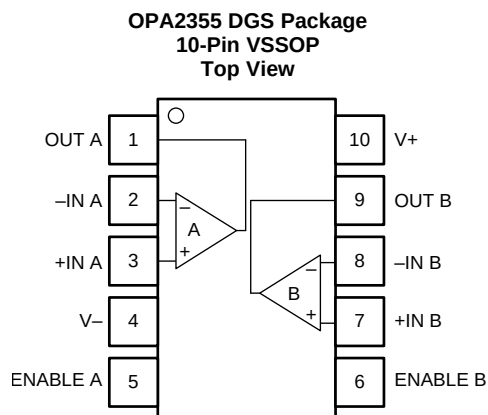
**OPA355 D Package
8-Pin SOIC
Top View**



- (1) Pin 1 of the SOT-23-6 is determined by orienting the package marking as indicated in the diagram.
(2) NC - no internal connection

Pin Functions: OPA355

NAME	PIN		I/O	DESCRIPTION
	SOT-23	SOIC		
ENABLE	5	8	—	Amplifier power down. Low = disabled, high = normal operation (pin must be driven)
IN+	3	3	I	Noninverting input pin
IN-	4	2	I	Inverting input pin
NC	—	1,5	—	Do not connect.
OUT	1	6	O	Output pin
V+	6	7	—	Positive power supply
V-	2	4	—	Negative power supply

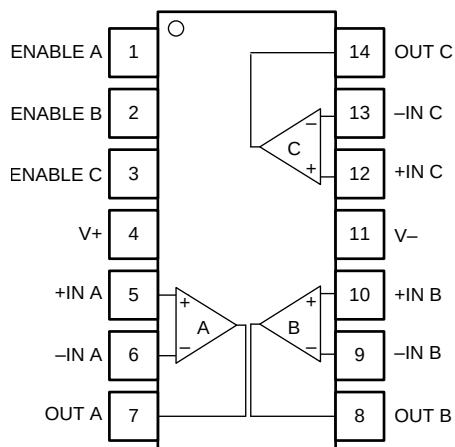


Pin Functions: OPA2355

PIN		I/O	DESCRIPTION
NAME	NO.		
ENABLE A	5	—	Amplifier power down, channel A. Low = disabled, high = normal operation (pin must be driven)
ENABLE B	6	—	Amplifier power down, channel B. Low = disabled, high = normal operation (pin must be driven)
+IN A	3	I	Noninverting input pin, channel A
+IN B	7	I	Noninverting input pin, channel B
–IN A	2	I	Inverting input pin, channel A
–IN B	8	I	Inverting input pin, channel B
OUT A	1	O	Output pin, channel A
OUT B	9	O	Output pin, channel B
V+	10	—	Positive power supply
V–	4	—	Negative power supply

OPA3355, OPA2355, OPA3355

JAJ5FB5E – MARCH 2001 – REVISED APRIL 2018

www.ti.com
**OPA3355 D and PW Packages
14-Pin SOIC, TSSOP
Top View**

Pin Functions: OPA3355

PIN		I/O	DESCRIPTION
NAME	NO.		
ENABLE A	1	—	Amplifier power down, channel A. Low = disabled, high = normal operation (pin must be driven)
ENABLE B	2	—	Amplifier power down, channel B. Low = disabled, high = normal operation (pin must be driven)
ENABLE C	3	—	Amplifier power down, channel C. Low = disabled, high = normal operation (pin must be driven)
+IN A	5	I	Noninverting input pin, channel A
+IN B	10	I	Noninverting input pin, channel B
+IN C	12	I	Noninverting input pin, channel C
–IN A	6	I	Inverting input pin, channel A
–IN B	9	I	Inverting input pin, channel B
–IN C	13	I	Inverting input pin, channel C
OUT A	7	O	Output, channel A
OUT B	8	O	Output channel B
OUT C	14	O	Output, channel C
V+	4	—	Positive power supply
V–	11	—	Negative power supply

7 Specifications

7.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

		MIN	MAX	UNIT
Supply voltage	V+ to V–		7.5	V
Signal input terminals	Voltage	(V–) – 0.5	(V+) + 0.5	V
	Current		10	mA
Output short circuit ⁽²⁾		Continuous		
Operating temperature		–55	150	°C
Junction temperature			160	°C
Lead temperature (soldering, 10 seconds)			300	°C
Storage temperature range, T _{stg}		–65	150	°C

- (1) Stresses above *Absolute Maximum Ratings* may cause permanent damage. Exposure to absolute maximum conditions for extended periods may degrade device reliability. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those specified is not implied.

- (2) Short-circuit to ground, one amplifier per package.

7.2 ESD Ratings

		VALUE	UNIT
V _(ESD) Electrostatic discharge	Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001 ⁽¹⁾	±2000	V
	Charged-device model (CDM), per JEDEC specification JESD22-C101 ⁽²⁾	±250	

- (1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process. Manufacturing with less than 500-V HBM is possible with the necessary precautions. Pins listed as ±2000 V may actually have higher performance.

- (2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process. Manufacturing with less than 250-V CDM is possible with the necessary precautions. Pins listed as ±250 V may actually have higher performance.

7.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

	MIN	NOM	MAX	UNIT
V _S Total supply voltage	2.7		5.5	V
T _A Ambient temperature	–40	25	125	°C

7.4 Thermal Information: OPA355

THERMAL METRIC ⁽¹⁾		OPA355		UNIT
		D (SOIC)	DBV (SOT-23)	
		8 PINS	6 PINS	
R _{θJA}	Junction-to-ambient thermal resistance	136.3	166.1	°C/W
R _{θJC(top)}	Junction-to-case (top) thermal resistance	76.7	104.3	°C/W
R _{θJB}	Junction-to-board thermal resistance	79.8	38.7	°C/W
ψ _{JT}	Junction-to-top characterization parameter	26.3	23.4	°C/W
ψ _{JB}	Junction-to-board characterization parameter	79	38.5	°C/W
R _{θJC(bot)}	Junction-to-case (bottom) thermal resistance	—	—	°C/W

(1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC Package Thermal Metrics](#) application report.

7.5 Thermal Information: OPA2355

THERMAL METRIC ⁽¹⁾		OPA2355	UNIT
		DGS (VSSOP)	
		10 PINS	
R _{θJA}	Junction-to-ambient thermal resistance	171.1	°C/W
R _{θJC(top)}	Junction-to-case (top) thermal resistance	58	°C/W
R _{θJB}	Junction-to-board thermal resistance	92.9	°C/W
ψ _{JT}	Junction-to-top characterization parameter	6.7	°C/W
ψ _{JB}	Junction-to-board characterization parameter	91.2	°C/W
R _{θJC(bot)}	Junction-to-case (bottom) thermal resistance	—	°C/W

(1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC Package Thermal Metrics](#) application report.

7.6 Thermal Information: OPA3355

THERMAL METRIC ⁽¹⁾		OPA3355		UNIT
		D (SOIC)	PW (TSSOP)	
		14 PINS	14 PINS	
R _{θJA}	Junction-to-ambient thermal resistance	85.3	113.3	°C/W
R _{θJC(top)}	Junction-to-case (top) thermal resistance	41.4	38	°C/W
R _{θJB}	Junction-to-board thermal resistance	41.5	58.1	°C/W
ψ _{JT}	Junction-to-top characterization parameter	8.3	2.8	°C/W
ψ _{JB}	Junction-to-board characterization parameter	41.2	57.3	°C/W
R _{θJC(bot)}	Junction-to-case (bottom) thermal resistance	—	—	°C/W

(1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC Package Thermal Metrics](#) application report.

7.7 Electrical Characteristics: $V_S = 2.7\text{ V to }5.5\text{ V}$ (Single-Supply)

at $T_A = 25^\circ\text{C}$, $R_F = 604\ \Omega$, $R_L = 150\ \Omega$, and connected to $V_S / 2$, (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
OFFSET VOLTAGE						
V _{OS}	Input offset voltage	V _S = 5 V		±2	±9	mV
		T _A = −40°C to +125°C			±15	
dV _{OS} /dT	Input offset voltage vs temperature	T _A = −40°C to +125°C		±7		μV/°C
	Input offset voltage vs power supply			±80	±350	μV/V
INPUT BIAS CURRENT						
I _B	Input bias current			3	±50	pA
I _{OS}	Input offset current			±1	±50	pA
NOISE						
	Input noise voltage density	f = 1 MHz		5.8		nV/√Hz
	Current noise density	f = 1 MHz		50		fA/√Hz
INPUT VOLTAGE RANGE						
V _{CM}	Common-mode voltage range		(V−) − 0.1	(V+) − 1.5		V
CMRR	Common-mode rejection ratio	V _S = 5.5 V, −0.1 V < V _{CM} < 4 V	66	80		dB
		V _S = 5.5 V, −0.1 V < V _{CM} < 4 V T _A = −40°C to +125°C	66			dB
INPUT IMPEDANCE						
	Differential			10 ¹³ 1.5		Ω pF
	Common-mode			10 ¹³ 1.5		Ω pF
OPEN-LOOP GAIN						
	Open-loop gain	V _S = 5 V, 0.3 V < V _O < 4.7 V	84	92		dB
		OPA355: V _S = 5 V, 0.3 V < V _O < 4.7 V T _A = −40°C to +125°C	80			dB
		OPA2355, OPA3355: V _S = 5 V, 0.4 V < V _O < 4.6 V	80			dB
FREQUENCY RESPONSE						
f _{−3dB}	Small-signal bandwidth	G = 1, V _O = 100 mVp-p, R _F = 0 Ω		450		MHz
		G = 2, V _O = 100 mVp-p, R _L = 50 Ω		100		MHz
		G = 2, V _O = 100 mVp-p, R _L = 150 Ω		170		MHz
		G = 2, V _O = 100 mVp-p, R _L = 1 kΩ		200		MHz
GBW	Gain-bandwidth product	G = 10, R _L = 1 kΩ		200		MHz
f _{0.1dB}	Bandwidth for 0.1-dB gain flatness	G = 2, V _O = 100 mVp-p, R _F = 560 Ω		75		MHz
SR	Slew rate	V _S = 5 V, G = 2, 4-V output step		300 / −360		V/μs
	Rise and fall time	G = 2, V _O = 200 Vp-p, 10% to 90%		2.4		ns
		G = 2, V _O = 2 Vp-p, 10% to 90%		8		ns
	Settling time	0.1%: V _S = 5 V, G = 2, 2-V output step		30		ns
		0.01%: V _S = 5 V, G = 2, 2-V output step		120		ns
	Overload recovery time	V _{IN} × gain = V _S		8		ns
HARMONIC DISTORTION						
	Second harmonic	G = 2, f = 1 MHz, V _O = 2 Vp-p, R _L = 200 Ω		−81		dBc
	Third harmonic	G = 2, f = 1 MHz, V _O = 2 Vp-p, R _L = 200 Ω		−93		dBc
	Differential gain error	NTSC, R _L = 150 Ω		0.02		%

Electrical Characteristics: $V_S = 2.7\text{ V}$ to 5.5 V (Single-Supply) (continued)

 at $T_A = 25^\circ\text{C}$, $R_F = 604\ \Omega$, $R_L = 150\ \Omega$, and connected to $V_S / 2$, (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
Differential phase error		NTSC, R _L = 150 Ω		0.05		°
Channel-to-channel crosstalk		OPA2355: f = 5 MHz		−90		dB
		OPA3335: f = 5 MHz		−70		dB
OUTPUT						
Voltage output swing from rail		V _S = 5 V, R _L = 150 Ω, A _{OL} > 84 dB		0.2	0.3	V
		V _S = 5 V, R _L = 1 kΩ		0.1		V
I _O	Continuous output current ⁽¹⁾			±60		mA
	Peak output current ⁽¹⁾	V _S = 5 V		±100		mA
		V _S = 3 V		±80		mA
Closed-loop output impedance ⁽¹⁾		f < 100 kHz		0.02		Ω
POWER SUPPLY						
V _S	Specified voltage range		2.7		5.5	V
	Operating voltage range		2.5 to 5.5			V
I _Q	Quiescent current (per amplifier)	V _S = 5 V, enabled, I _O = 0		8.3	11	mA
		T _A = −40°C to +125°C			14	mA
SHUTDOWN						
Disabled (logic-LOW threshold)					0.8	V
Enabled (logic-HIGH threshold)			2			V
Enable time				100		ns
Disable time				30		ns
Shutdown current (per amplifier)		V _S = 5 V, disabled		3.4	6	μA
THERMAL SHUTDOWN						
Junction temperature		Shutdown		160		°C
		Reset from shutdown		140		
TEMPERATURE RANGE						
Specified range			−40		125	°C
Operating range			−55		150	°C
Storage range			−65		150	°C
θ _{JA}	Thermal resistance	SOT-23-6, VSSOP-10		150		°C/W
		SO-8		125		°C/W
		SO-14, TSSOP-14		100		°C/W

 (1) See [Output Voltage Swing vs Output Current](#).

7.8 Typical Characteristics

$T_A = 25^\circ\text{C}$, $V_S = 5\text{ V}$, $G = 2$, $R_F = 604\ \Omega$, and $R_L = 150\ \Omega$ connected to $V_S / 2$, (unless otherwise noted)

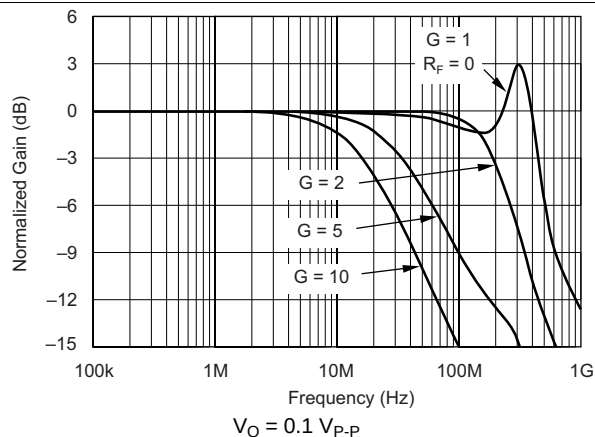


FIG 1. Noninverting Small-Signal Frequency Response

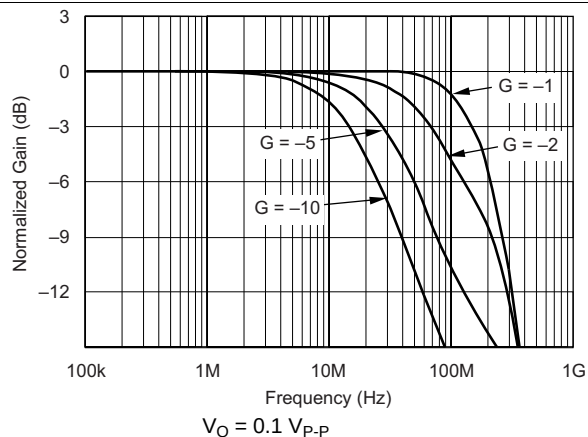


FIG 2. Inverting Small-Signal Frequency Response

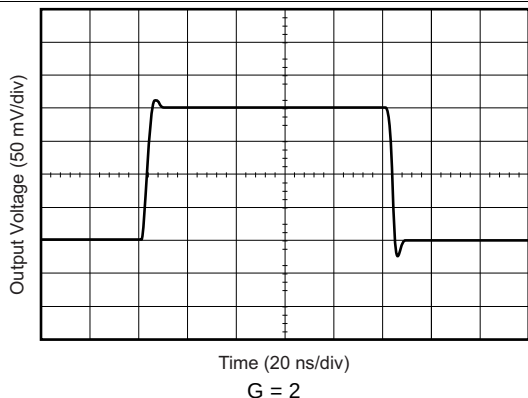


FIG 3. Noninverting Small-Signal Step Response

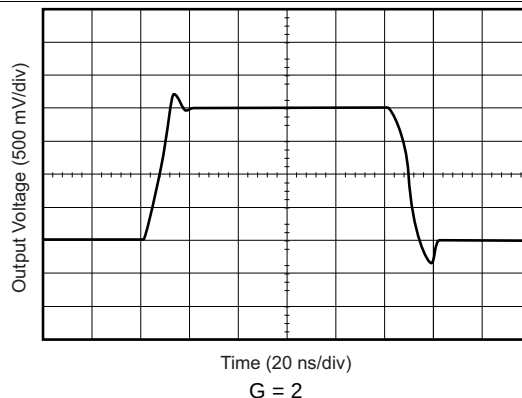


FIG 4. Noninverting Large-Signal Step Response

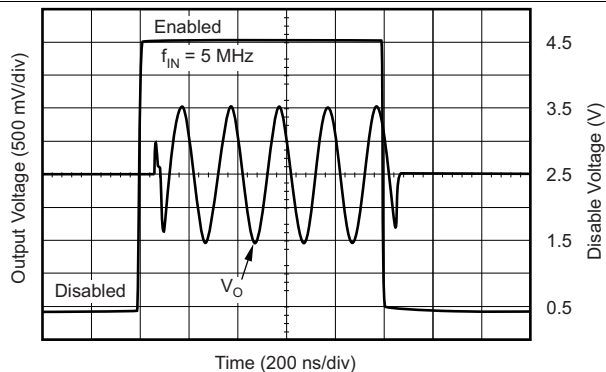


FIG 5. Large-Signal Disable and Enable Response

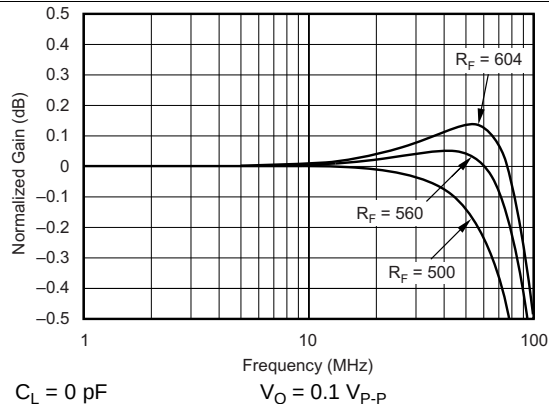


FIG 6. 0.1-dB Gain Flatness for Various R_F Values

Typical Characteristics (continued)

$T_A = 25^\circ\text{C}$, $V_S = 5\text{ V}$, $G = 2$, $R_F = 604\ \Omega$, and $R_L = 150\ \Omega$ connected to $V_S / 2$, (unless otherwise noted)

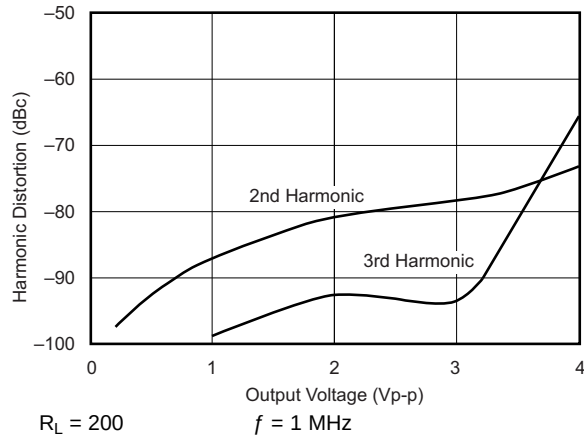


图 7. Harmonic Distortion vs Output Voltage

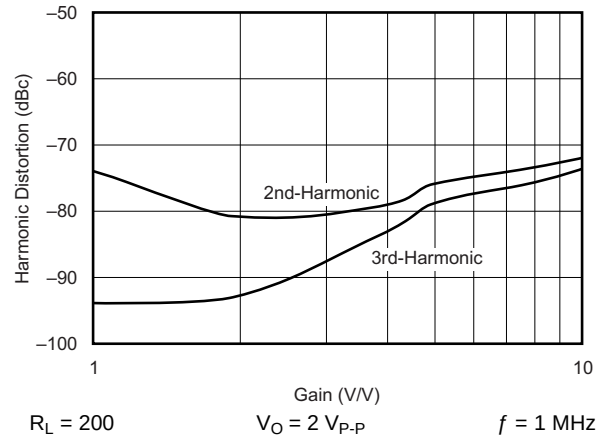


图 8. Harmonic Distortion vs Noninverting Gain

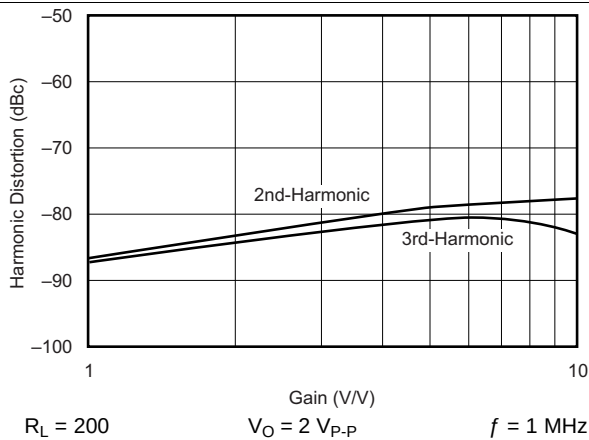


图 9. Harmonic Distortion vs Inverting Gain

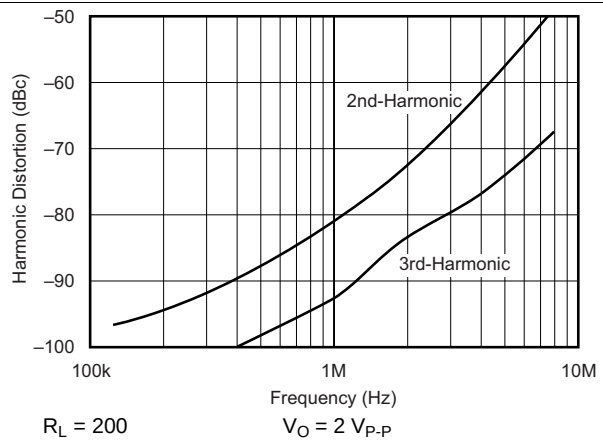


图 10. Harmonic Distortion vs Frequency

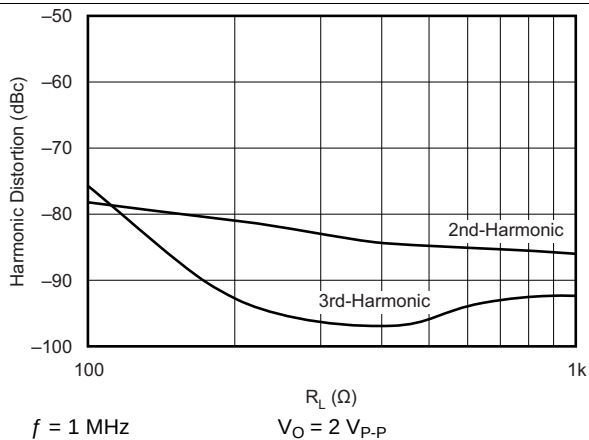


图 11. Harmonic Distortion vs Load Resistance

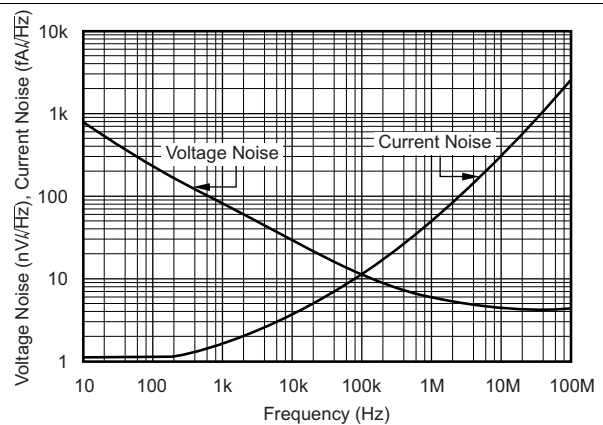


图 12. Input Voltage and Current Noise Spectral Density vs Frequency

Typical Characteristics (continued)

$T_A = 25^\circ\text{C}$, $V_S = 5\text{ V}$, $G = 2$, $R_F = 604\ \Omega$, and $R_L = 150\ \Omega$ connected to $V_S / 2$, (unless otherwise noted)

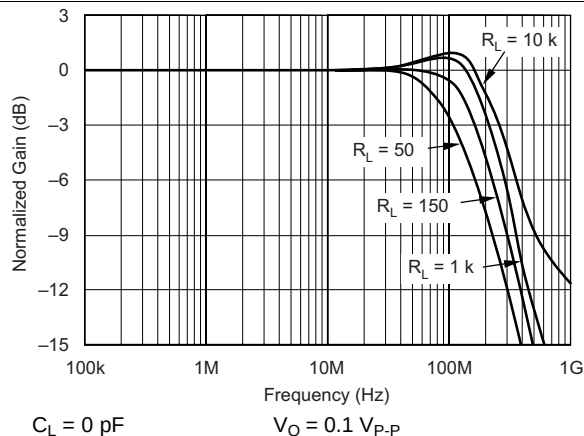


FIG 13. Frequency Response for Various R_L Values

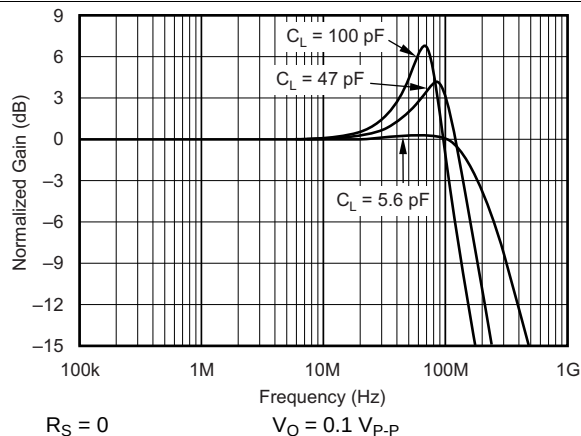


FIG 14. Frequency Response for Various C_L Values

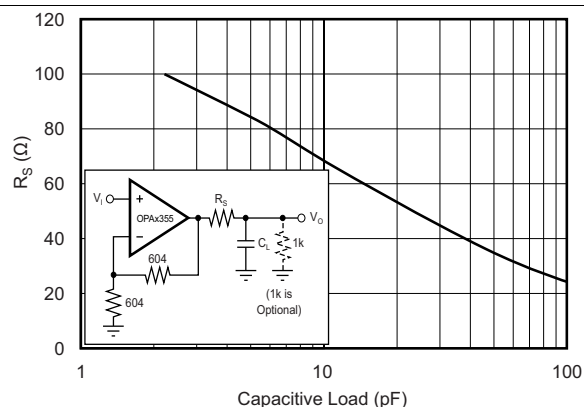


FIG 15. Recommended R_S Values vs Capacitive Load

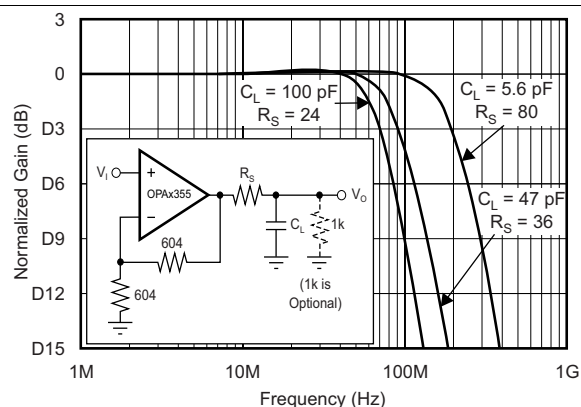


FIG 16. Frequency Response vs Capacitive Load

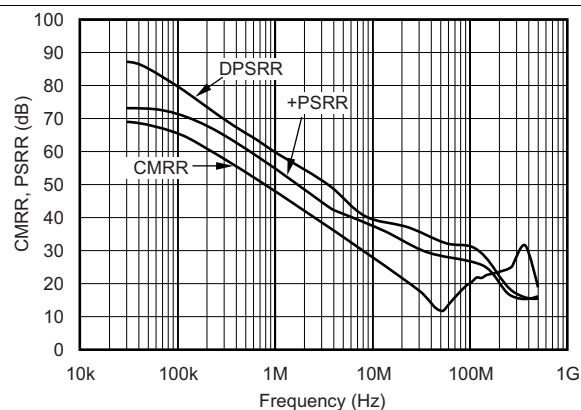


FIG 17. Common-Mode Rejection Ratio and Power-Supply Rejection Ratio vs Frequency

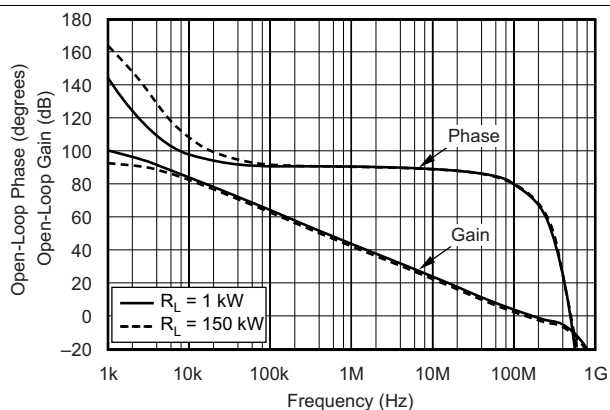


FIG 18. Open-Loop Gain and Phase

Typical Characteristics (continued)

$T_A = 25^\circ\text{C}$, $V_S = 5\text{ V}$, $G = 2$, $R_F = 604\ \Omega$, and $R_L = 150\ \Omega$ connected to $V_S / 2$, (unless otherwise noted)

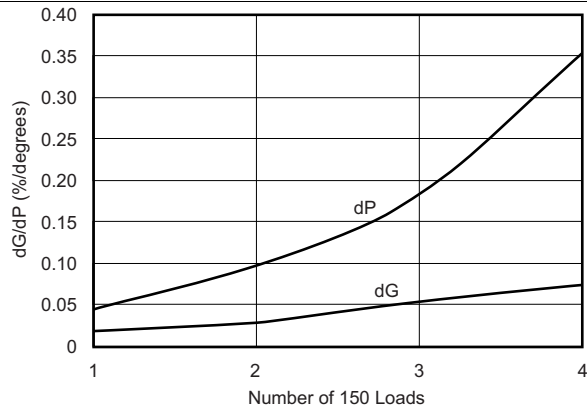


FIG 19. Composite Video Differential Gain and Phase

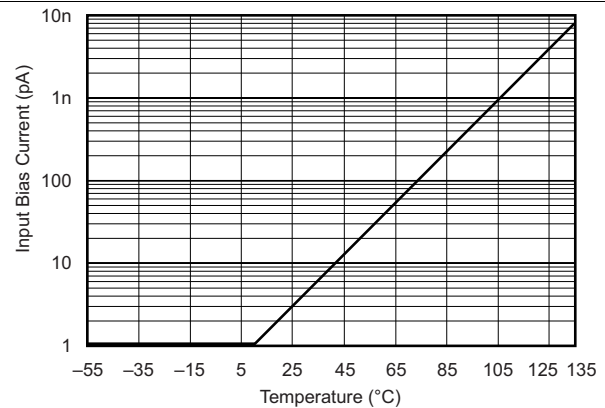


FIG 20. Input Bias Current vs Temperature

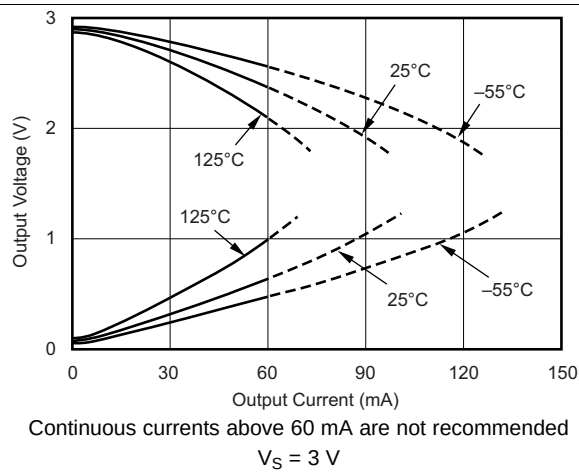


FIG 21. Output Voltage Swing vs Output Current

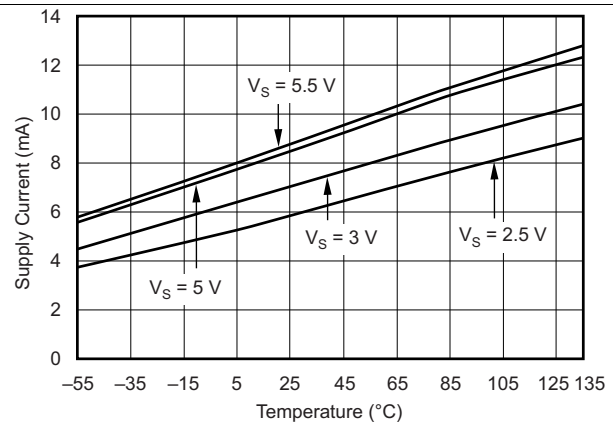


FIG 22. Supply Current vs Temperature

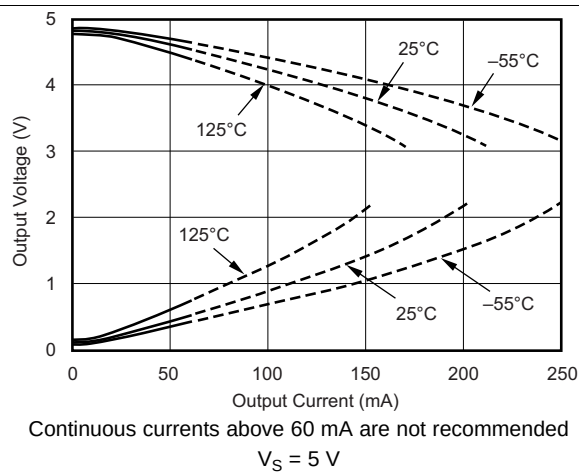


FIG 23. Output Voltage Swing vs Output Current

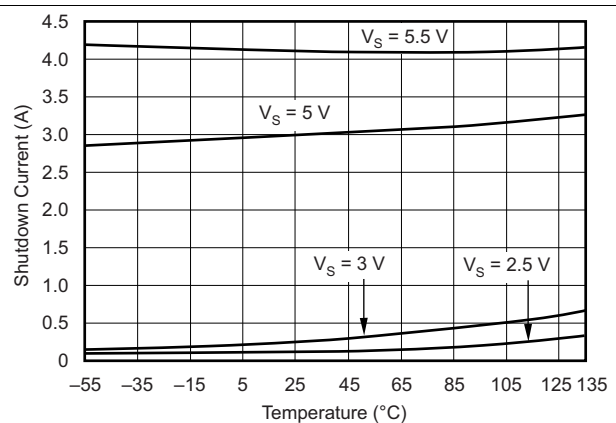


FIG 24. Shutdown Current vs Temperature

Typical Characteristics (continued)

$T_A = 25^\circ\text{C}$, $V_S = 5\text{ V}$, $G = 2$, $R_F = 604\ \Omega$, and $R_L = 150\ \Omega$ connected to $V_S / 2$, (unless otherwise noted)

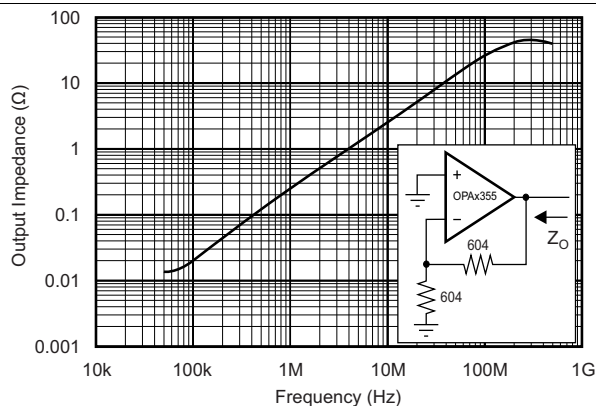
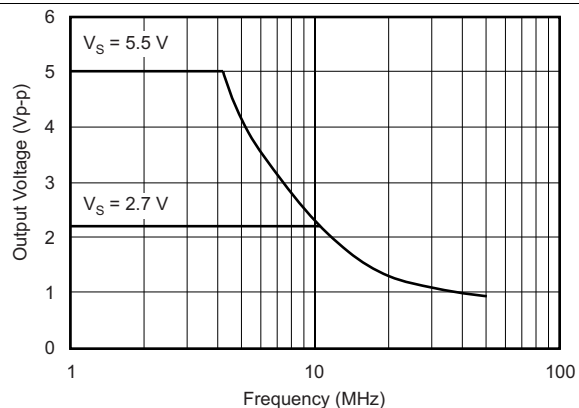


Figure 25. Closed-Loop Output Impedance vs Frequency



Maximum output voltage without slew-rate induced distortion

Figure 26. Maximum Output Voltage vs Frequency

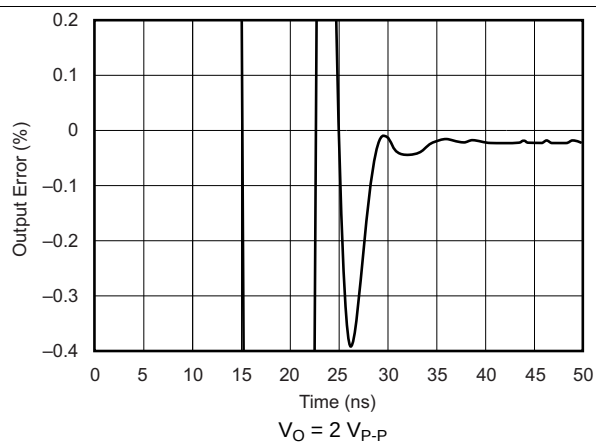


Figure 27. Output Settling Time to 0.1%

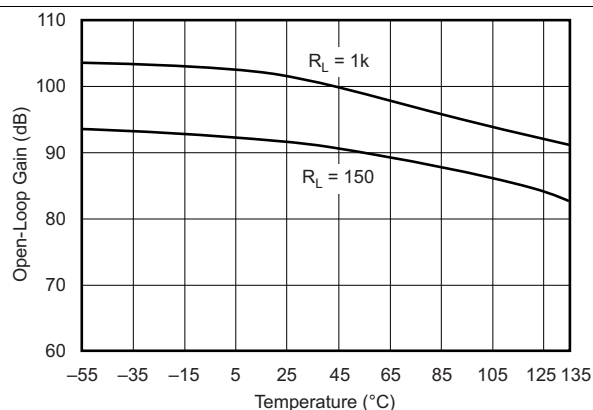


Figure 28. Open-Loop Gain vs Temperature

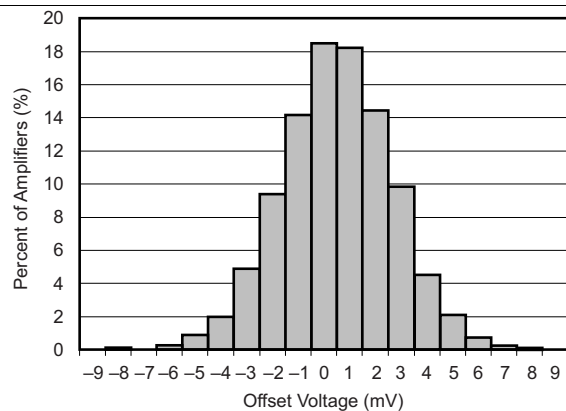


Figure 29. Offset Voltage Production Distribution

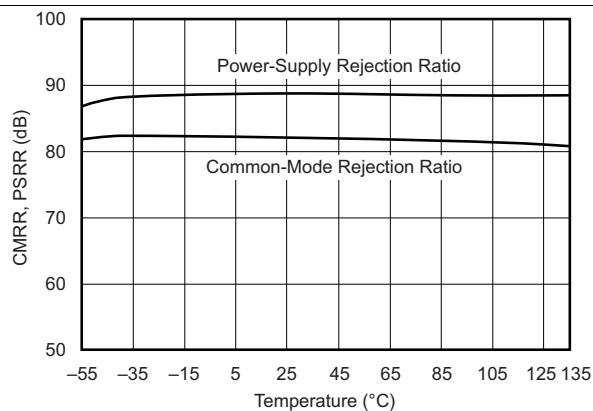


Figure 30. Common-Mode Rejection Ratio and Power-Supply Rejection Ratio vs Temperature

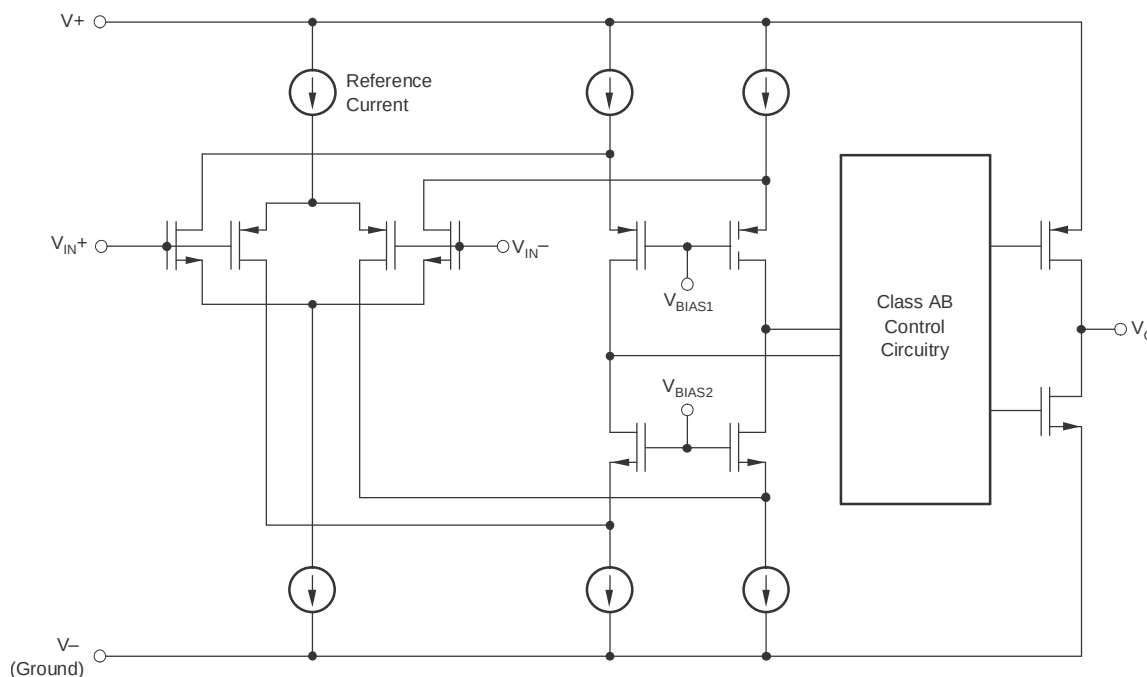
8 Detailed Description

8.1 Overview

The OPA355 series is a CMOS, high-speed, voltage-feedback, operational amplifier designed for video and other general-purpose applications. The series is available as a single, dual, or triple op amp. The family features a 200-MHz gain bandwidth and 360 V/ μ s slew rate, but the series is unity-gain stable and can operate as a 1 V/V voltage follower.

The input common-mode range includes ground, allowing the OPAX355 family to be used in virtually any single-supply application up to a supply voltage of 5.5 V.

8.2 Functional Block Diagram



8.3 Feature Description

8.3.1 Operating Voltage

The OPAX355 family is specified over a power-supply range of 2.7 V to 5.5 V (± 1.35 to ± 2.75 V). However, the supply voltage ranges from 2.5 to 5.5 V (± 1.25 to ± 2.75 V). Supply voltages higher than 7.5 V (absolute maximum) can permanently damage the amplifier.

Parameters that vary significantly over supply voltage or temperature are shown in the [Typical Characteristics](#) section of this data sheet.

8.3.2 Enable Function

The OPAX355 series is enabled by applying a TTL high-voltage level to the enable pin. Conversely, a TTL low-voltage level disables the amplifier, which reduces the supply current from 8.3 mA to 3.4 μ A per amplifier. This pin voltage is referenced to a single-supply ground. When using a split-supply, such as ± 2.5 V, the enable and disable voltage levels are referenced to V-. For portable battery-operated applications, this feature greatly reduces the average current and as a result, extends battery life.

The enable input is modeled as a CMOS input gate with a 100-k Ω pullup resistor to V+. The enable pin assumes a logic high and the amplifier turns on if the enable pin is left open.

Feature Description (continued)

The enable time is 100 ns and the disable time is 30 ns, which allows the OPAx355 series to operate as a *gated* amplifier, or to have the output multiplexed onto a common output bus. When disabled, the output assumes a high-impedance state.

8.3.3 Output Drive

The output stage supplies a high short-circuit current (typically over 200 mA). Therefore, an on-chip thermal shutdown circuit is provided to protect the OPAx355 series from dangerously-high junction temperatures. At 160°C, the protection circuit shuts down the amplifier. Normal operation resumes when the junction temperature cools to below 140°C.

注

Running a continuous DC current in excess of ± 60 mA is not recommended. See the *Output Voltage Swing vs Output Current* graphs (Figure 21 and Figure 22) in the *Typical Characteristics* section.

8.4 Device Functional Modes

The OPAx355 family is powered on when the supply is connected. The series operates as a single supply operational amplifier or dual supply amplifier depending on the application. The series is used with asymmetrical supplies as long as the differential voltage (V_- to V_+) is at least 1.8 V and no greater than 5.5 V (example: V_- set to -3.5 V and V_+ set to 1.5 V).

9 Application and Implementation

注

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

9.1 Application Information

The OPAx355 series is a CMOS, high-speed, voltage-feedback, operational amplifier (op amp) designed for general-purpose applications.

The amplifiers feature a 200-MHz gain bandwidth and 300-V/ μ s slew rate, but the devices are unity-gain stable and operate as a 1-V/V voltage follower.

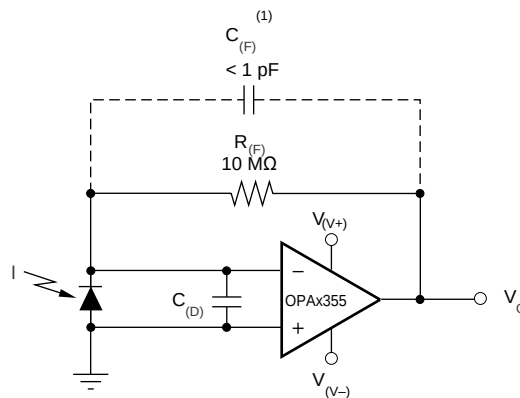
The input common-mode voltage range of the series includes ground, which allows the OPAx355 to be used in virtually any single-supply application up to a supply voltage of 5.5 V.

9.2 Typical Applications

9.2.1 Transimpedance Amplifier

Wide gain bandwidth, low input bias current, low input voltage, and current noise make the OPAx355 series a preferred wideband photodiode transimpedance amplifier family. Low voltage noise is important because photodiode capacitance causes the effective noise gain of the circuit to increase at high frequencies.

The key elements to a transimpedance design, as shown in [Figure 31](#), are the expected diode capacitance ($C_{[D]}$), which must include the parasitic input common-mode and differential-mode input capacitance (4 pF + 5 pF), the desired transimpedance gain ($R_{[FB]}$), and the gain-bandwidth (GBW) for the OPAx355 family (20 MHz). With these three variables set, the feedback capacitor value ($C_{[FB]}$) controls the frequency response. $C_{[FB]}$ includes the stray capacitance of $R_{[FB]}$, which is 0.2 pF for a typical surface-mount resistor.



(1) $C_{[FB]}$ is optional to prevent gain peaking. $C_{[FB]}$ includes the stray capacitance of $R_{[FB]}$.

Figure 31. Dual-Supply Transimpedance Amplifier

9.2.1.1 Design Requirements

PARAMETER	VALUE
Supply voltage $V_{(V+)}$	2.5 V
Supply voltage $V_{(V-)}$	-2.5 V

9.2.1.2 Detailed Design Procedure

To achieve a maximally-flat, second-order Butterworth frequency response, set the feedback pole to:

$$\frac{1}{2 \times \pi \times R_{(FB)} \times C_{(FB)}} = \sqrt{\frac{GBW}{4 \times \pi \times R_{(FB)} \times C_{(D)}}} \quad (1)$$

Use 式 2 to calculate the bandwidth.

$$f_{(-3 \text{ dB})} = \sqrt{\frac{GBW}{2 \times \pi \times R_{(FB)} \times C_{(D)}}} \quad (2)$$

For other transimpedance bandwidths, consider the high-speed CMOS OPA380 (90-MHz GBW), OPA354 (100-MHz GBW), OPA300 (180-MHz GBW), OPA355 (200-MHz GBW), or OPA656 and OPA657 (400-MHz GBW).

For single-supply applications, the +INx input is biased with a positive DC voltage to allow the output to reach true zero when the photodiode is not exposed to any light, and respond without the added delay that results from coming out of the negative rail. 图 32 shows this configuration. This bias voltage appears across the photodiode, providing a reverse bias for faster operation.

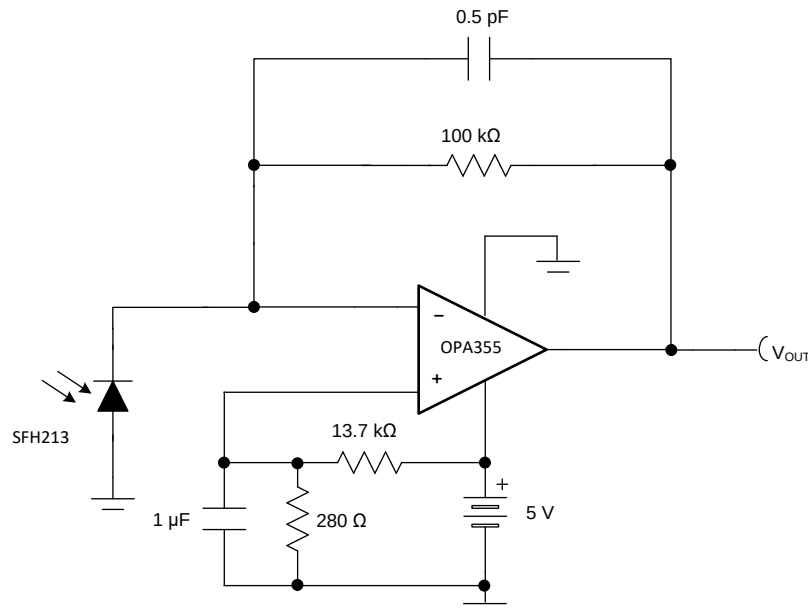


图 32. Single-Supply Transimpedance Amplifier

For additional information, see [Compensate Transimpedance Amplifiers Intuitively](#).

9.2.1.2.1 Optimizing The Transimpedance Circuit

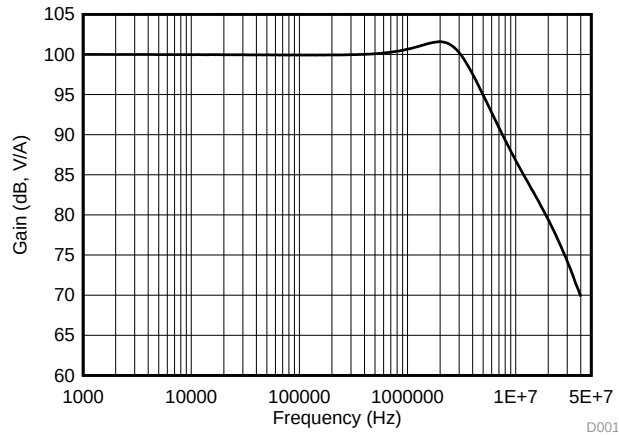
To achieve the best performance, select components according to the following guidelines:

1. For lowest noise, select $R_{(FB)}$ to create the total required gain. Using a lower value for $R_{(FB)}$ and adding gain after the transimpedance amplifier generally results in poorer noise performance. $R_{(FB)}$ produces noise that increases with the square root of $R_{(FB)}$, whereas the signal increases linearly. Therefore, signal-to-noise ratio improves when all the required gain is placed in the transimpedance stage.
2. Minimize photodiode capacitance and stray capacitance at the summing junction (inverting input). This capacitance causes the voltage noise of the op amp to amplify (increasing amplification at high frequencies). Using a low-noise voltage source to reverse-bias a photodiode can significantly reduce the capacitance. Smaller photodiodes have lower capacitance. Use optics to concentrate light on a small photodiode.
3. Noise increases with increased bandwidth. Only use the required circuit bandwidth. Use a capacitor across the $R_{(FB)}$ to limit bandwidth, even if a capacitor is not required for stability.
4. Circuit board leakage can degrade the performance of an otherwise well-designed amplifier. Clean the circuit board carefully. Control leakage by using a circuit board guard trace that encircles the summing junction and

drives at the same voltage.

For additional information, see [Noise Analysis of FET Transimpedance Amplifiers](#) and [Noise Analysis for High-Speed Op Amps](#)).

9.2.1.3 Application Curve

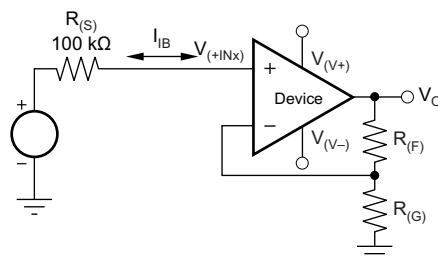


–3 dB bandwidth is 4.56 MHz

✕ 33. AC Transfer Function

9.2.2 High-Impedance Sensor Interface

Many sensors have high source impedances that may range up to 10 M Ω , or even higher. The output signal of sensors often must be amplified or otherwise conditioned by an amplifier. The input bias current of this amplifier loads the sensor output and causes a voltage drop across the source resistance, ✕ 34 shows ($V_{(+INx)} = V_S - I_{(BIAS)} \times R_{(S)}$.) The last term ($I_{(BIAS)} \times R_{(S)}$) shows the voltage drop across $R_{(S)}$. To prevent errors introduced to the system as a result of this voltage, use an op amp with low input bias current with high-impedance sensors. This low current keeps the $I_{(BIAS)} \times R_{(S)}$ error contribution less than the input voltage noise of the amplifier so that input voltage noise is not the dominant noise factor. The OPAx355 op amps feature low input bias current (typically 200 fA), and as a result, a preferred choice for these applications.

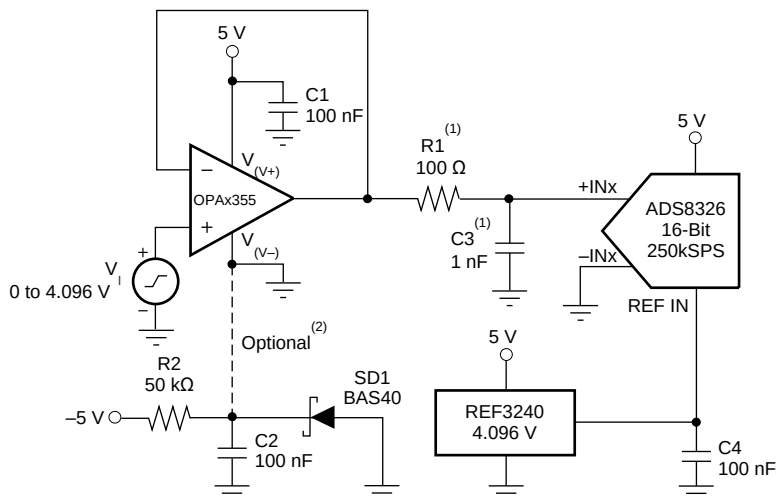


✕ 34. Noise as a Result of $I_{(BIAS)}$

9.2.3 Driving ADCs

The OPAx355 op amps are designed to drive sampling analog-to-digital converters (ADCs) with sampling speeds up to 1 MSPS. The zero-crossover distortion input stage topology allows the OPAx355 series to drive ADCs without degrading differential linearity and THD.

The OPAx355 series buffers the ADC switched input capacitance and resulting charge injection while providing signal gain. [Figure 35](#) shows the OPAx355 series configured to drive the [ADS8326](#).



(1) Suggested value; may require adjustment based on specific application.

(2) Single-supply applications lose a small number of ADC codes near ground as a result of op amp output swing limitation. If a negative power supply is available, this simple circuit creates a -0.3-V supply to allow output swing to true ground potential.

Figure 35. Driving the ADS8326

9.2.4 Active Filter

The OPAx355 series is designed for active filter applications that require a wide bandwidth, fast slew rate, low-noise, single-supply operational amplifier. [Figure 36](#) shows a 500 kHz, second-order, low-pass filter using the multiple-feedback (MFB) topology. The components are selected to provide a maximally-flat Butterworth response. Beyond the cutoff frequency, roll-off is -40 dB/dec . The Butterworth response is preferred for applications requiring predictable gain characteristics, such as the anti-aliasing filter used in front of an ADC.

One point to observe when considering the MFB filter is that the output is inverted, relative to the input. If this inversion is not required, or not desired, a noninverting output can be achieved through one of the following options:

1. Adding an inverting amplifier
2. Adding an additional second-order MFB stage
3. Using a noninverting filter topology, such as the Sallen-Key (see [Figure 37](#)).

MFB and Sallen-Key, low-pass and high-pass filter synthesis is quickly accomplished using TI's [FilterPro™](#) program. This software is available as a free download at www.ti.com.

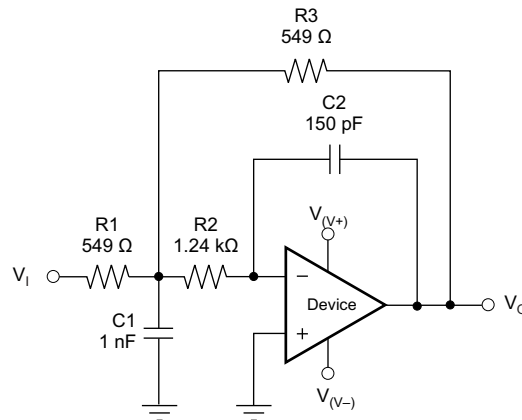


图 36. Second-Order Butterworth 500-kHz Low-Pass Filter

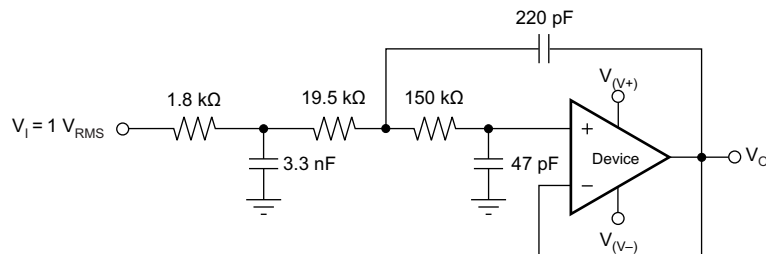


图 37. OPAx355 Configured as a Three-Pole, 20-kHz, Sallen-Key Filter

9.3 Video

The OPAx355 output stage is capable of driving a standard back-terminated 75-Ω video cable. By back-terminating a transmission line, the line does not exhibit a capacitive load to the driver. A properly back-terminated 75-Ω cable does not appear as capacitance; the cable presents only a 150-Ω resistive load to the OPAx355 output.

The OPAx355 can be used as an amplifier for RGB graphic signals, which have a voltage of zero at the video black level by offsetting and AC-coupling the signal, as shown in [图 38](#).

Video (continued)

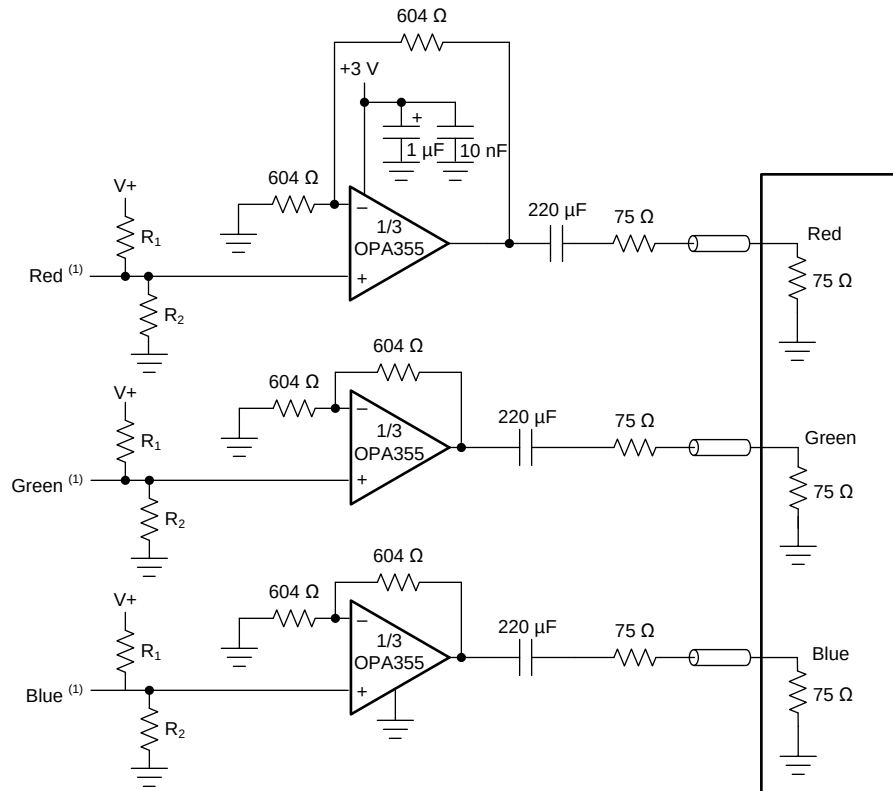


FIG 38. RGB Cable Driver

9.4 Wideband Video Multiplexing

One common application for video speed amplifiers which include an enable pin is to wire multiple amplifier outputs together, then select which one of several possible video inputs to source onto a single line. This simple wired-OR video multiplexer can be easily implemented using the OPA357; see FIG 39.

Wideband Video Multiplexing (continued)

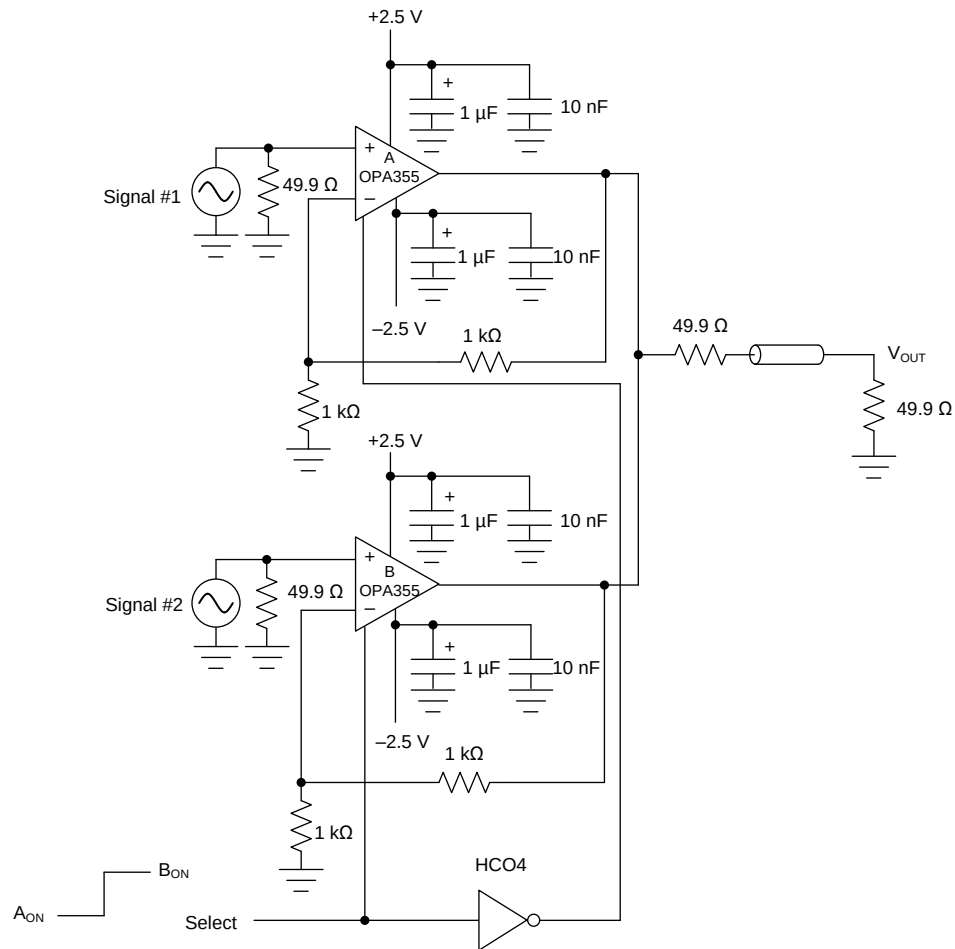


FIG 39. Multiplexed Output

10 Power Supply Recommendations

The OPAx355 is specified for operation from 2.7 to 5.5 V (± 1.35 to ± 2.75 V); many specifications apply from -40°C to $+125^{\circ}\text{C}$. Parameters that can exhibit significant variance with regard to operating voltage or temperature are shown in the [Typical Characteristics](#) section.

Place 0.1- μF bypass capacitors close to the power-supply pins to reduce errors coupling in from noisy or high-impedance power supplies. For more detailed information on bypass capacitor placement, see the [Layout Guidelines](#) section.

Power dissipation depends on power-supply voltage, signal and load conditions. With DC signals, power dissipation is equal to the product of output current times the voltage across the conducting output transistor, $V_S - V_O$. Minimize power dissipation by using the lowest possible power-supply voltage required to ensure the required output voltage swing.

For resistive loads, the maximum power dissipation occurs at a DC output voltage of one-half the power-supply voltage. Dissipation with AC signals is lower. *Power Amplifier Stress and Power Handling Limitations* explains how to calculate or measure power dissipation with unusual signals and loads, and is available on www.ti.com.

Any tendency to activate the thermal protection circuit indicates excessive power dissipation or an inadequate heat sink. For reliable operation, limit junction temperature to 150°C maximum. To estimate the margin of safety in a complete design, increase the ambient temperature to trigger the thermal protection at 160°C . The thermal protection must trigger more than 35°C above the maximum expected ambient condition of the application.

11 Layout

11.1 Layout Guidelines

Good high-frequency printed-circuit board (PCB) layout techniques must be used for the OPAx355 amplifiers. Generous use of ground planes, short direct-signal traces, and a preferred bypass capacitor located at the V+ pin ensures clean and stable operation. Large areas of copper help dissipate heat generated within the amplifiers in normal operation.

Sockets are not recommended for use with any high-speed amplifier.

A 10-nF ceramic bypass capacitor is the minimum recommended value; adding a 1- μF or larger tantalum capacitor in parallel is beneficial when driving a low-resistance load. Providing adequate bypass capacitance is essential to achieving very low harmonic and intermodulation distortion.

11.2 Layout Example

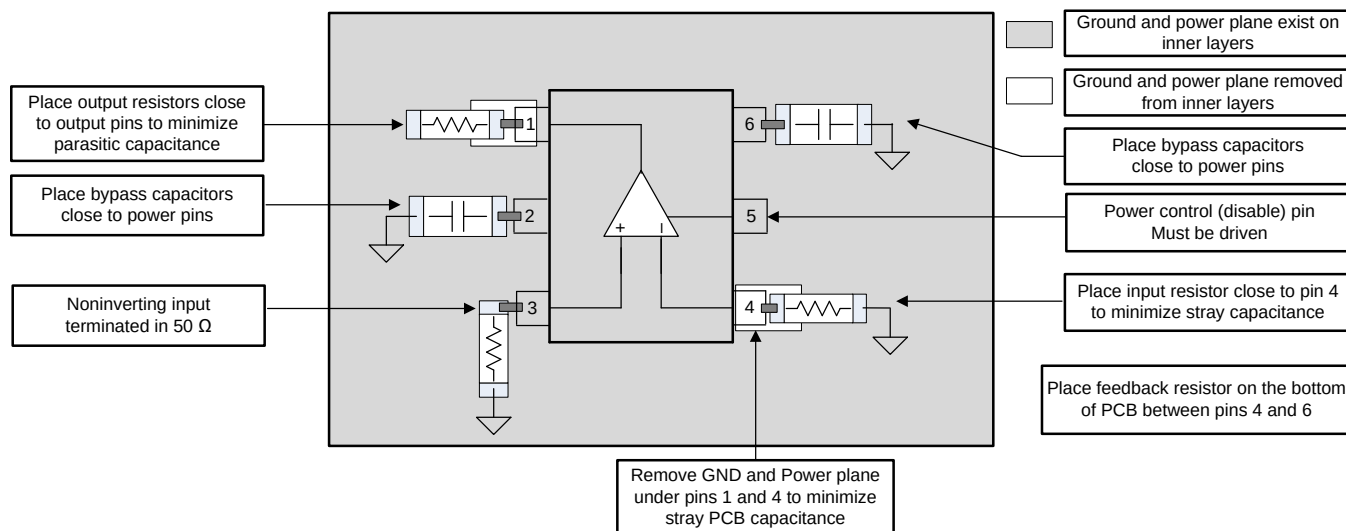


图 40. Layout Example

12 デバイスおよびドキュメントのサポート

12.1 関連リンク

次の表に、クイック・アクセス・リンクを示します。カテゴリには、技術資料、サポートおよびコミュニティ・リソース、ツールとソフトウェア、およびご注文へのクイック・アクセスが含まれます。

表 1. 関連リンク

製品	プロダクト・フォルダ	ご注文はこちら	技術資料	ツールとソフトウェア	サポートとコミュニティ
OPA355	ここをクリック	ここをクリック	ここをクリック	ここをクリック	ここをクリック
OPA2355	ここをクリック	ここをクリック	ここをクリック	ここをクリック	ここをクリック
OPA3355	ここをクリック	ここをクリック	ここをクリック	ここをクリック	ここをクリック

12.2 ドキュメントの更新通知を受け取る方法

ドキュメントの更新についての通知を受け取るには、**ti.com**のデバイス製品フォルダを開いてください。右上の隅にある「通知を受け取る」をクリックして登録すると、変更されたすべての製品情報に関するダイジェストを毎週受け取れます。変更の詳細については、修正されたドキュメントに含まれている改訂履歴をご覧ください。

12.3 コミュニティ・リソース

The following links connect to TI community resources. Linked contents are provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's [Terms of Use](#).

TI E2E™ オンライン・コミュニティ *TIのE2E (Engineer-to-Engineer) コミュニティ*。エンジニア間の共同作業を促進するために開設されたものです。e2e.ti.comでは、他のエンジニアに質問し、知識を共有し、アイデアを検討して、問題解決に役立てることができます。

設計サポート *TIの設計サポート* 役に立つE2Eフォーラムや、設計サポート・ツールをすばやく見つけることができます。技術サポート用の連絡先情報も参照できます。

12.4 商標

E2E is a trademark of Texas Instruments.

FilterPro is a trademark of Texas Instruments Incorporated.

All other trademarks are the property of their respective owners.

12.5 静電気放電に関する注意事項



すべての集積回路は、適切なESD保護方法を用いて、取扱いと保存を行うようにして下さい。

静電気放電はわずかな性能の低下から完全なデバイスの故障に至るまで、様々な損傷を与えます。高精度の集積回路は、損傷に対して敏感であり、極めてわずかなパラメータの変化により、デバイスに規定された仕様に適合しなくなる場合があります。

12.6 Glossary

SLYZ022 — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

13 メカニカル、パッケージ、および注文情報

以降のページには、メカニカル、パッケージ、および注文に関する情報が記載されています。この情報は、そのデバイスについて利用可能な最新のデータです。このデータは予告なく変更されることがあり、ドキュメントが改訂される場合もあります。本データシートのブラウザ版を使用されている場合は、画面左側の説明をご覧ください。

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
OPA2355DGSA/250	Active	Production	VSSOP (DGS) 10	250 SMALL T&R	Yes	NIPDAUAG	Level-2-260C-1 YEAR	-40 to 125	D55
OPA2355DGSA/250.B	Active	Production	VSSOP (DGS) 10	250 SMALL T&R	Yes	NIPDAUAG	Level-2-260C-1 YEAR	-40 to 125	D55
OPA2355DGSA/250G4	Active	Production	VSSOP (DGS) 10	250 SMALL T&R	Yes	NIPDAUAG	Level-2-260C-1 YEAR	-40 to 125	D55
OPA3355EA/250	Active	Production	TSSOP (PW) 14	250 SMALL T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	OPA 3355EA
OPA3355EA/250.B	Active	Production	TSSOP (PW) 14	250 SMALL T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	OPA 3355EA
OPA3355EA/2K5	Active	Production	TSSOP (PW) 14	2500 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	OPA 3355EA
OPA3355EA/2K5.B	Active	Production	TSSOP (PW) 14	2500 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	OPA 3355EA
OPA3355UA	Active	Production	SOIC (D) 14	50 TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	OPA3355UA
OPA3355UA.B	Active	Production	SOIC (D) 14	50 TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	OPA3355UA
OPA355NA/250	Active	Production	SOT-23 (DBV) 6	250 SMALL T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	C55
OPA355NA/250.B	Active	Production	SOT-23 (DBV) 6	250 SMALL T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	C55
OPA355NA/250G4	Active	Production	SOT-23 (DBV) 6	250 SMALL T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	C55
OPA355NA/3K	Active	Production	SOT-23 (DBV) 6	3000 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	C55
OPA355NA/3K.B	Active	Production	SOT-23 (DBV) 6	3000 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	C55
OPA355NA/3KG4	Active	Production	SOT-23 (DBV) 6	3000 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	C55
OPA355UA	Active	Production	SOIC (D) 8	75 TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	OPA 355UA
OPA355UA.B	Active	Production	SOIC (D) 8	75 TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	OPA 355UA
OPA355UA/2K5	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	OPA 355UA
OPA355UA/2K5.B	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	OPA 355UA
OPA355UAG4	Active	Production	SOIC (D) 8	75 TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	OPA 355UA

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

(2) Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) RoHS values: Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

(4) Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

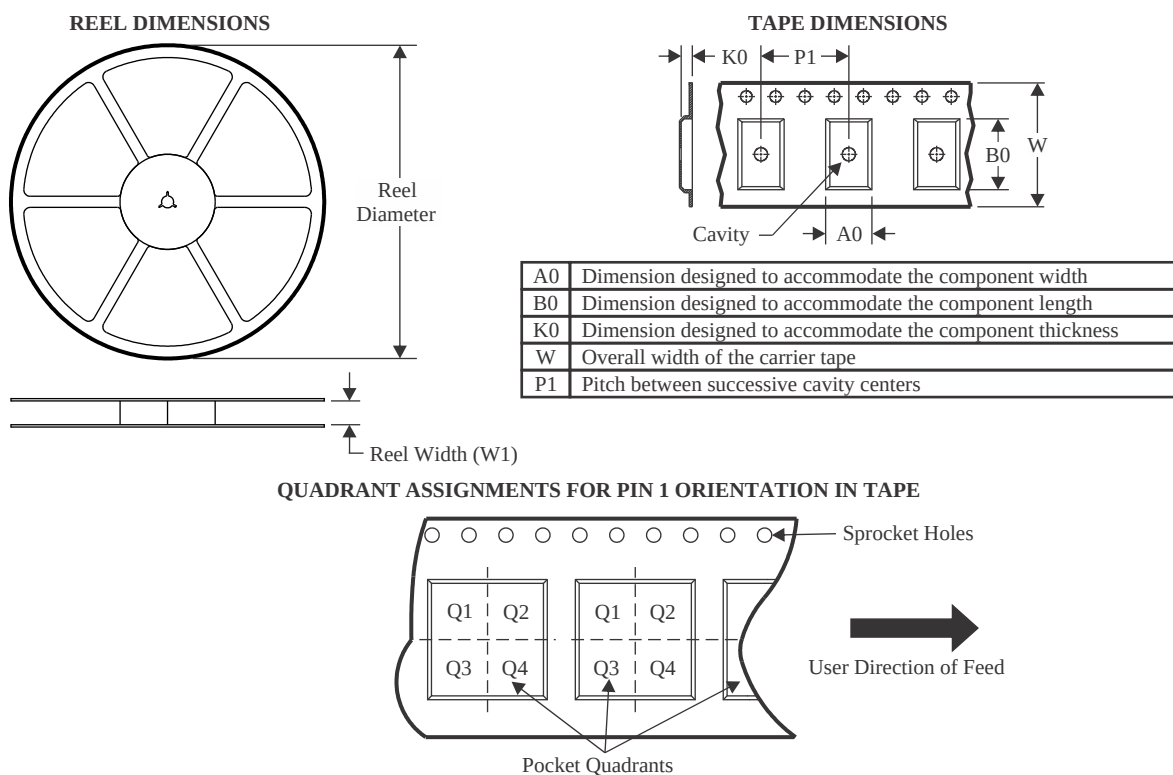
OTHER QUALIFIED VERSIONS OF OPA355 :

- Automotive : [OPA355-Q1](#)

NOTE: Qualified Version Definitions:

- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects

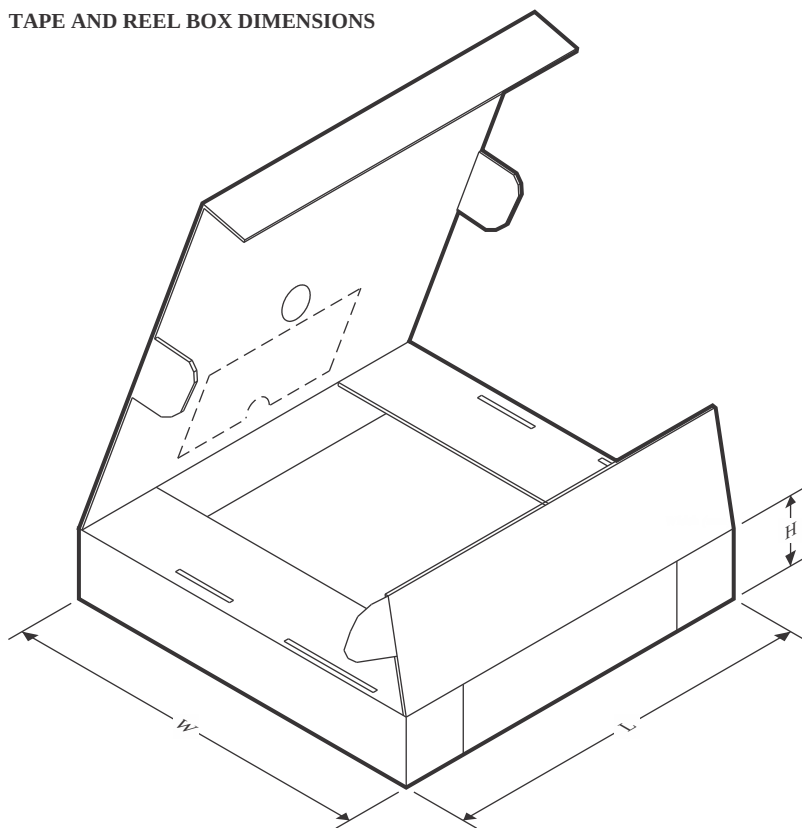
TAPE AND REEL INFORMATION



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
OPA2355DGSA/250	VSSOP	DGS	10	250	180.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
OPA3355EA/250	TSSOP	PW	14	250	180.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
OPA3355EA/2K5	TSSOP	PW	14	2500	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
OPA355NA/250	SOT-23	DBV	6	250	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
OPA355NA/3K	SOT-23	DBV	6	3000	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
OPA355UA/2K5	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1

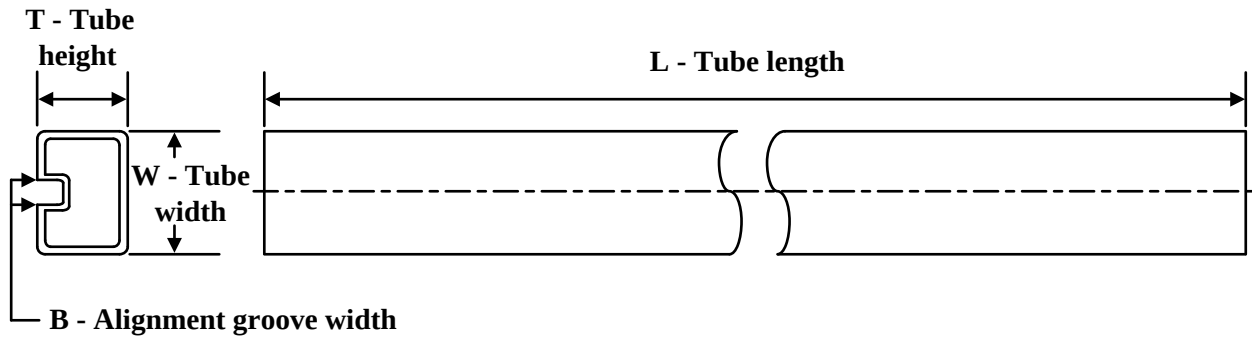
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

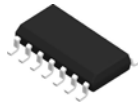
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
OPA2355DGSA/250	VSSOP	DGS	10	250	213.0	191.0	35.0
OPA3355EA/250	TSSOP	PW	14	250	213.0	191.0	35.0
OPA3355EA/2K5	TSSOP	PW	14	2500	353.0	353.0	32.0
OPA355NA/250	SOT-23	DBV	6	250	445.0	220.0	345.0
OPA355NA/3K	SOT-23	DBV	6	3000	445.0	220.0	345.0
OPA355UA/2K5	SOIC	D	8	2500	353.0	353.0	32.0

TUBE

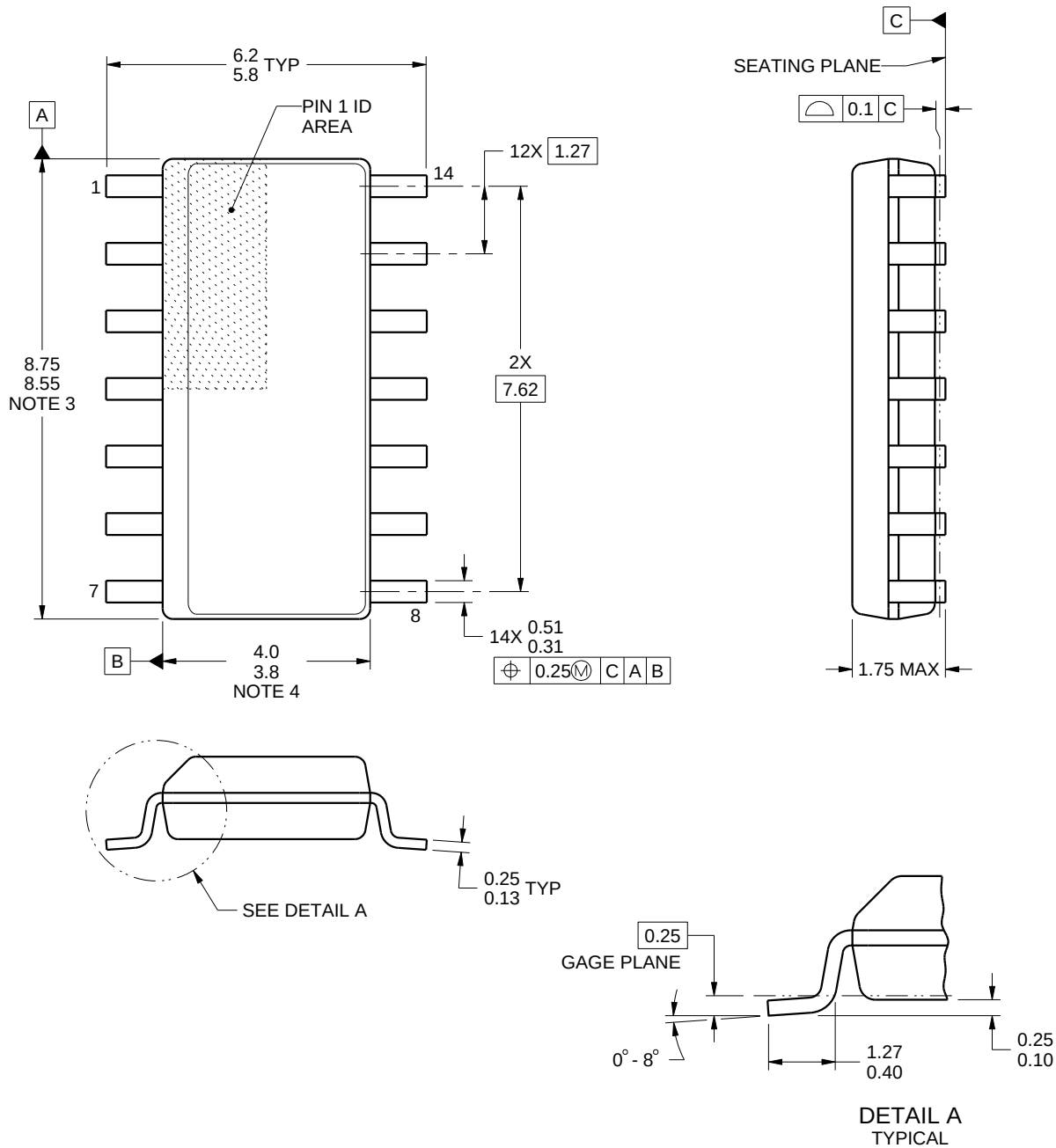


*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
OPA3355UA	D	SOIC	14	50	506.6	8	3940	4.32
OPA3355UA.B	D	SOIC	14	50	506.6	8	3940	4.32
OPA355UA	D	SOIC	8	75	506.6	8	3940	4.32
OPA355UA.B	D	SOIC	8	75	506.6	8	3940	4.32
OPA355UAG4	D	SOIC	8	75	506.6	8	3940	4.32

D0014A**PACKAGE OUTLINE****SOIC - 1.75 mm max height**

SMALL OUTLINE INTEGRATED CIRCUIT



4220718/A 09/2016

NOTES:

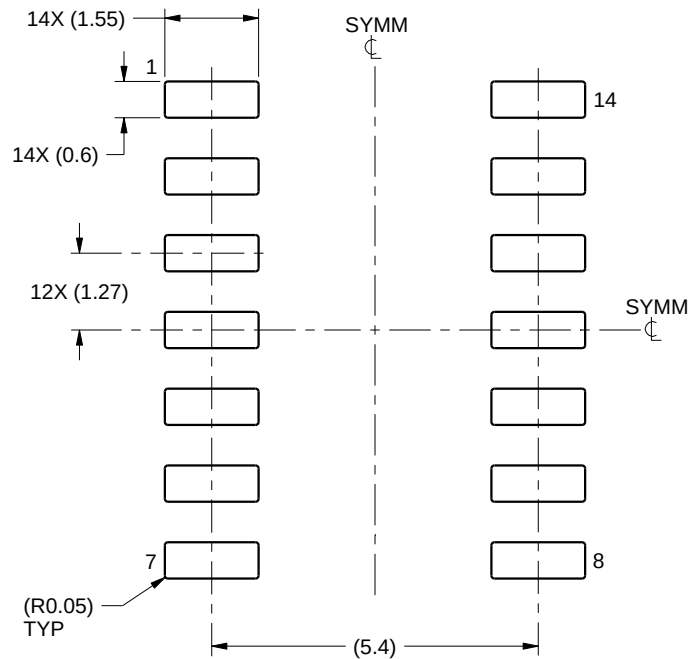
1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm, per side.
5. Reference JEDEC registration MS-012, variation AB.

EXAMPLE BOARD LAYOUT

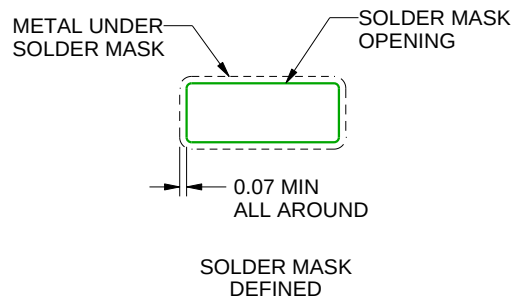
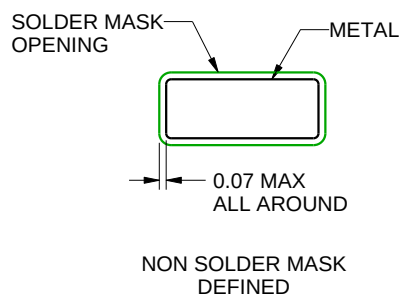
D0014A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



LAND PATTERN EXAMPLE
SCALE:8X



SOLDER MASK DETAILS

4220718/A 09/2016

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

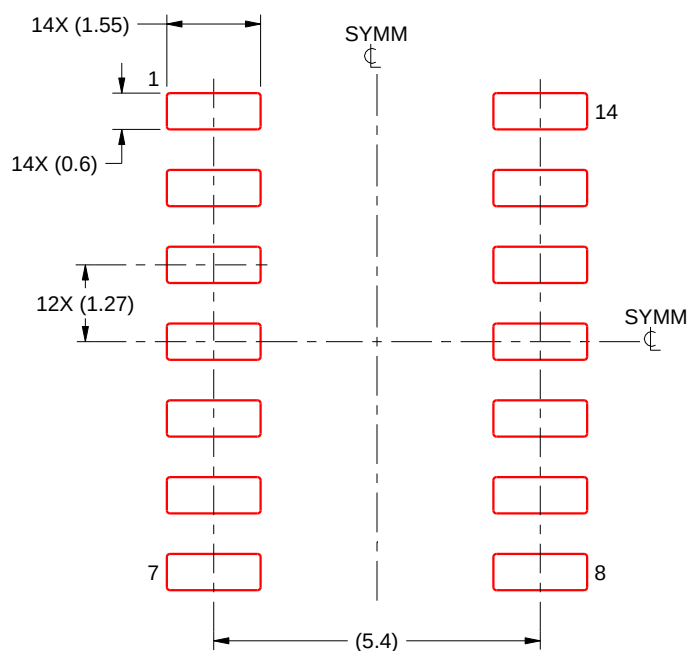
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

D0014A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT

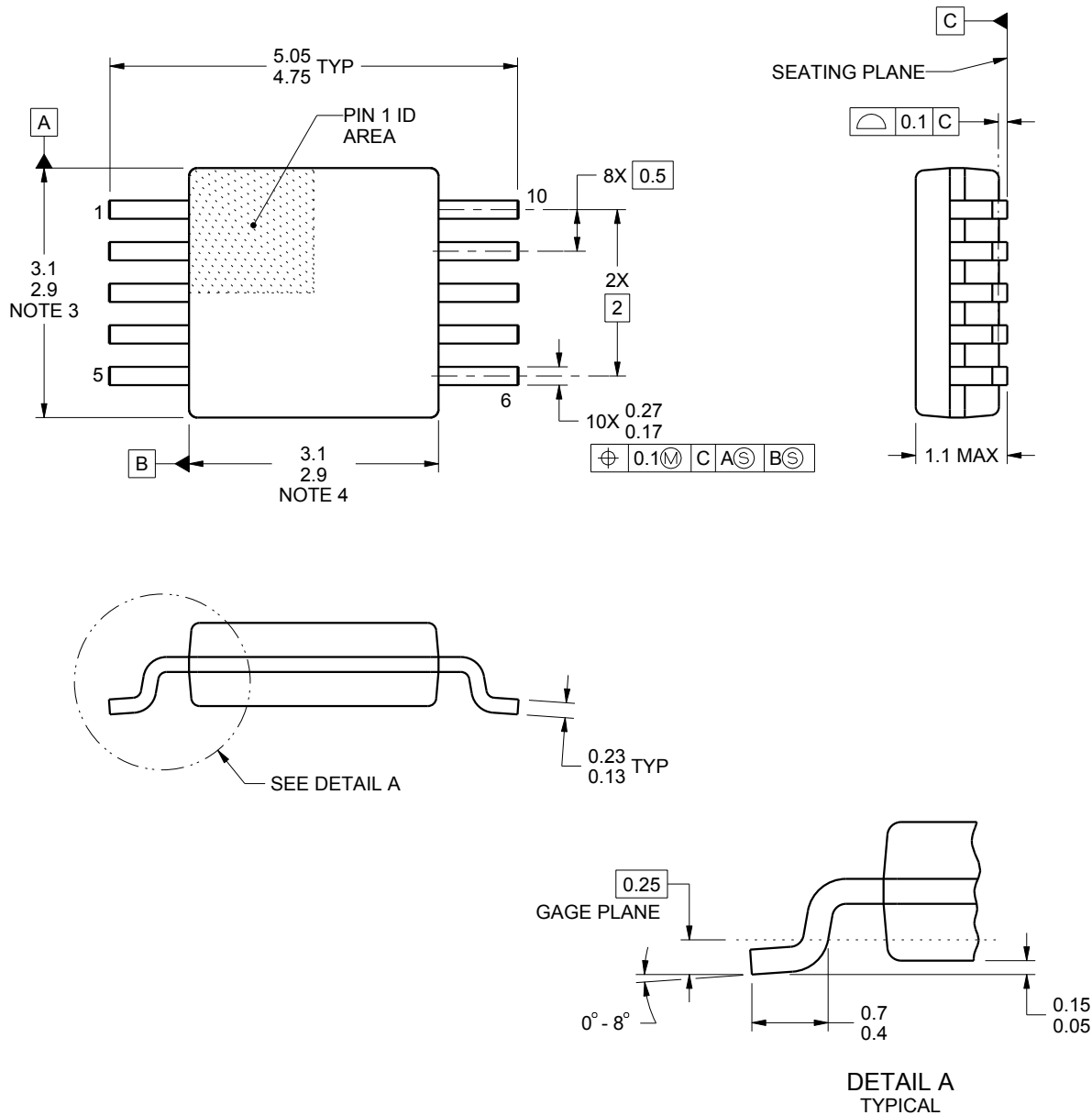


SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:8X

4220718/A 09/2016

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.



4221984/A 05/2015

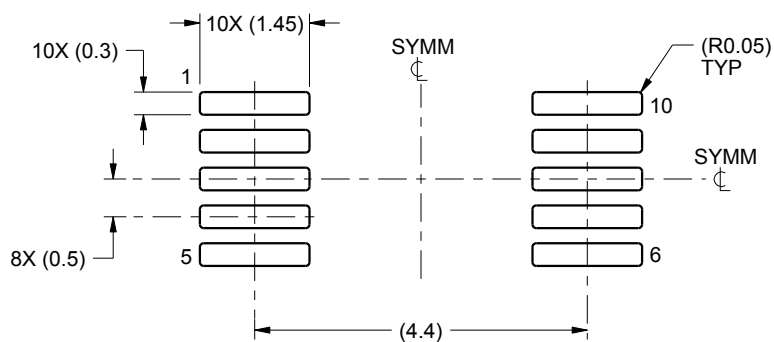
NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-187, variation BA.

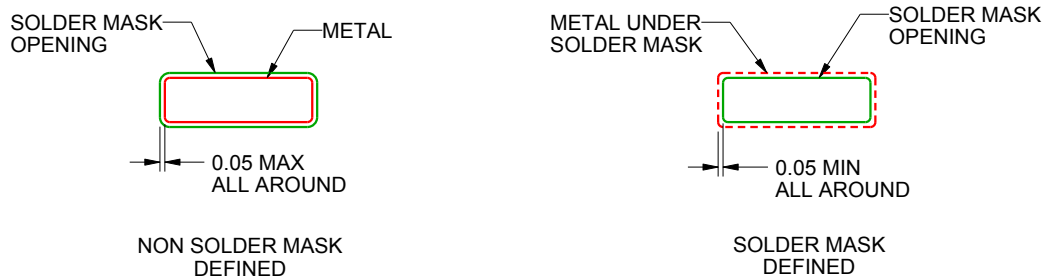
DGS0010A

VSSOP - 1.1 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
SCALE:10X



SOLDER MASK DETAILS
NOT TO SCALE

4221984/A 05/2015

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

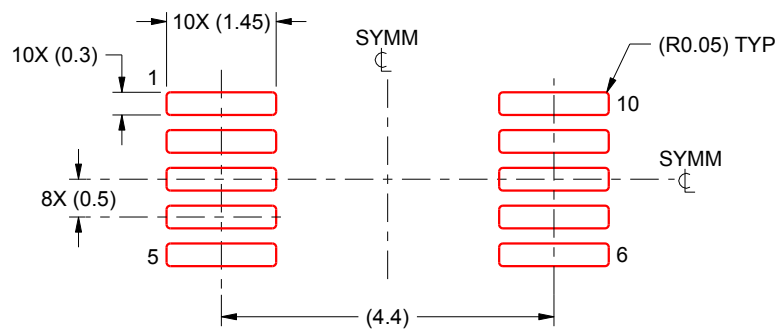
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DGS0010A

VSSOP - 1.1 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:10X

4221984/A 05/2015

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.



PACKAGE OUTLINE

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



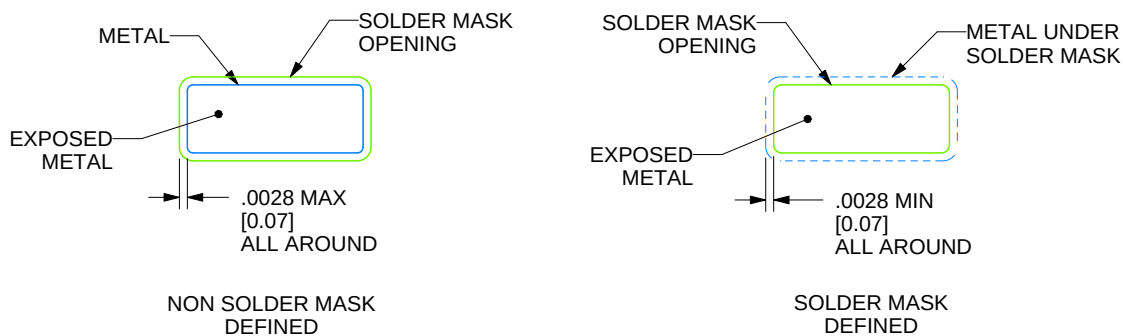
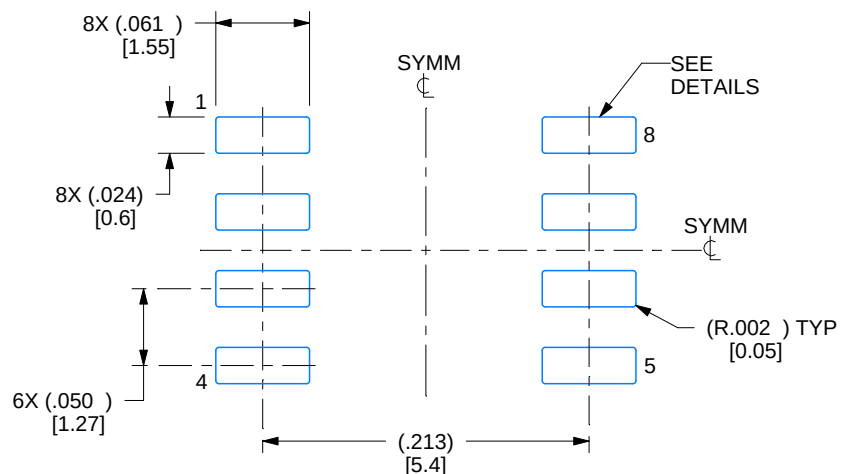
1. Linear dimensions are in inches [millimeters]. Dimensions in parenthesis are for reference only. Controlling dimensions are in inches. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 [0.15] per side.
4. This dimension does not include interlead flash.
5. Reference JEDEC registration MS-012, variation AA.

EXAMPLE BOARD LAYOUT

D0008A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



4214825/C 02/2019

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

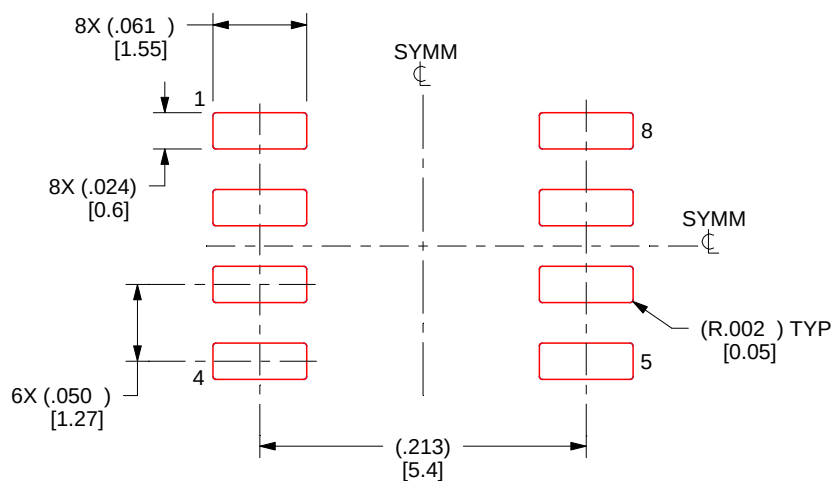
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

D0008A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



SOLDER PASTE EXAMPLE
BASED ON .005 INCH [0.125 MM] THICK STENCIL
SCALE:8X

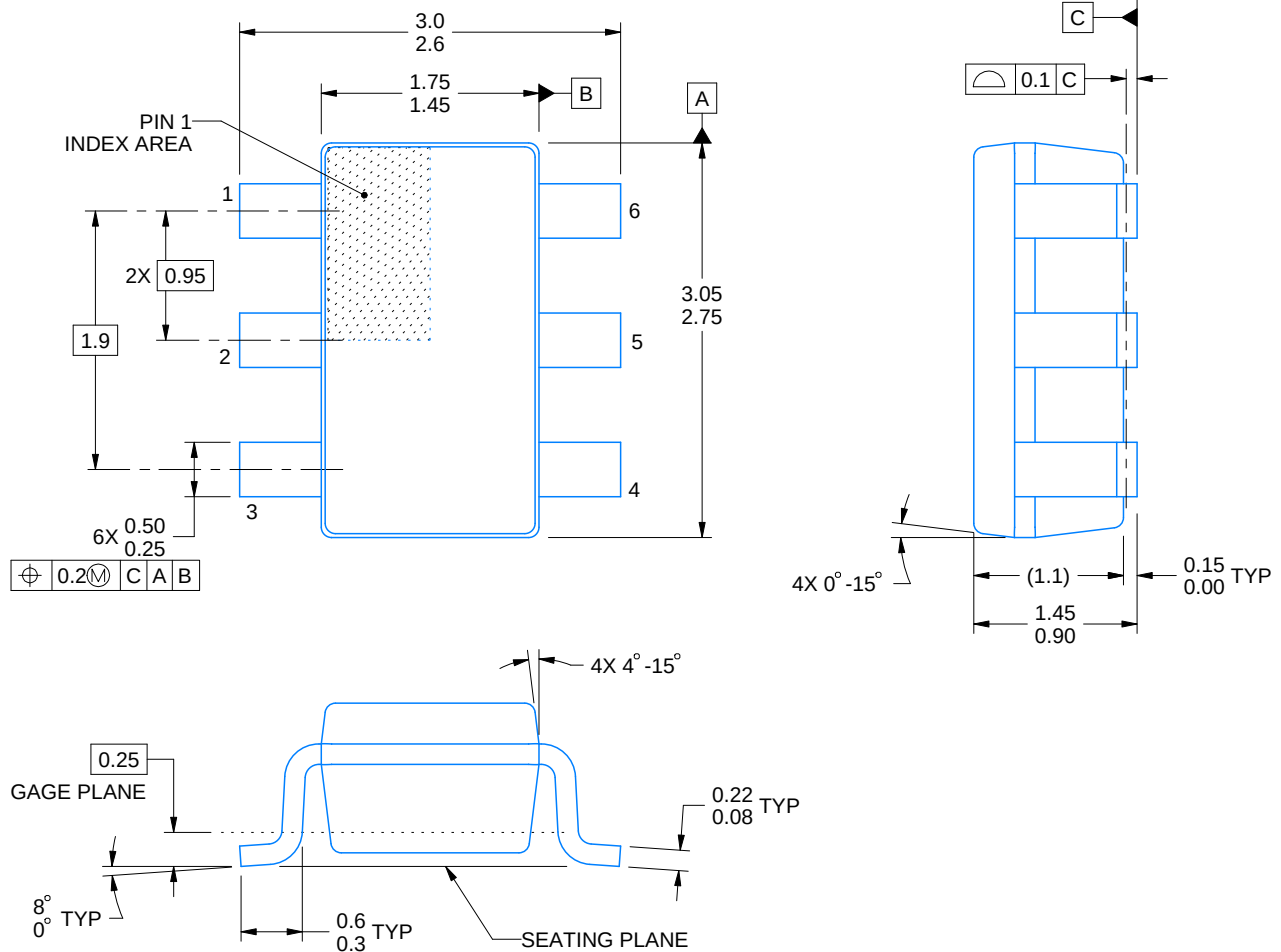
4214825/C 02/2019

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

DBV0006A**PACKAGE OUTLINE****SOT-23 - 1.45 mm max height**

SMALL OUTLINE TRANSISTOR



4214840/G 08/2024

NOTES:

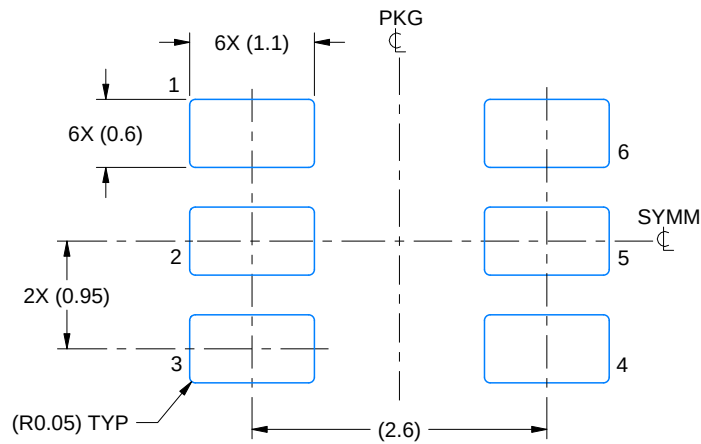
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.25 per side.
4. Leads 1,2,3 may be wider than leads 4,5,6 for package orientation.
5. Reference JEDEC MO-178.

EXAMPLE BOARD LAYOUT

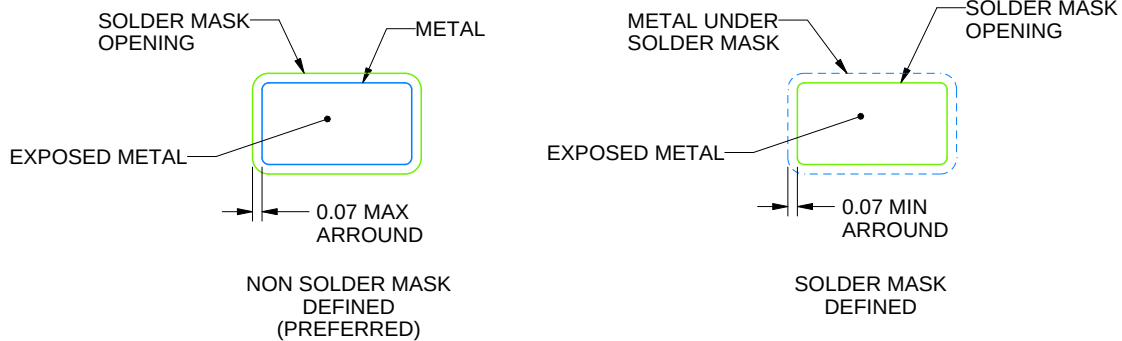
DBV0006A

SOT-23 - 1.45 mm max height

SMALL OUTLINE TRANSISTOR



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:15X



SOLDER MASK DETAILS

4214840/G 08/2024

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

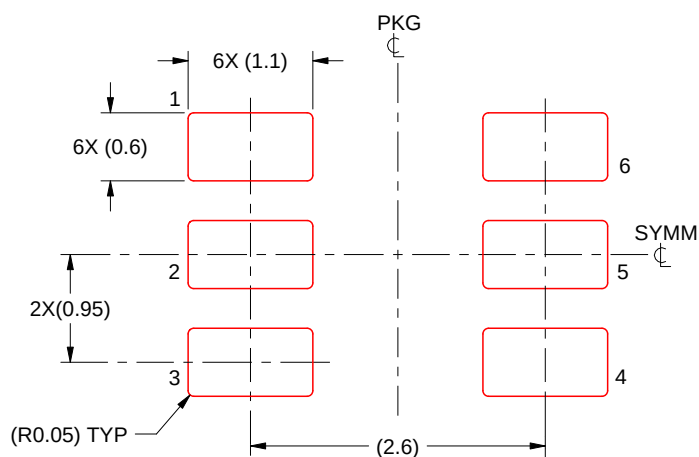
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DBV0006A

SOT-23 - 1.45 mm max height

SMALL OUTLINE TRANSISTOR



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:15X

4214840/G 08/2024

NOTES: (continued)

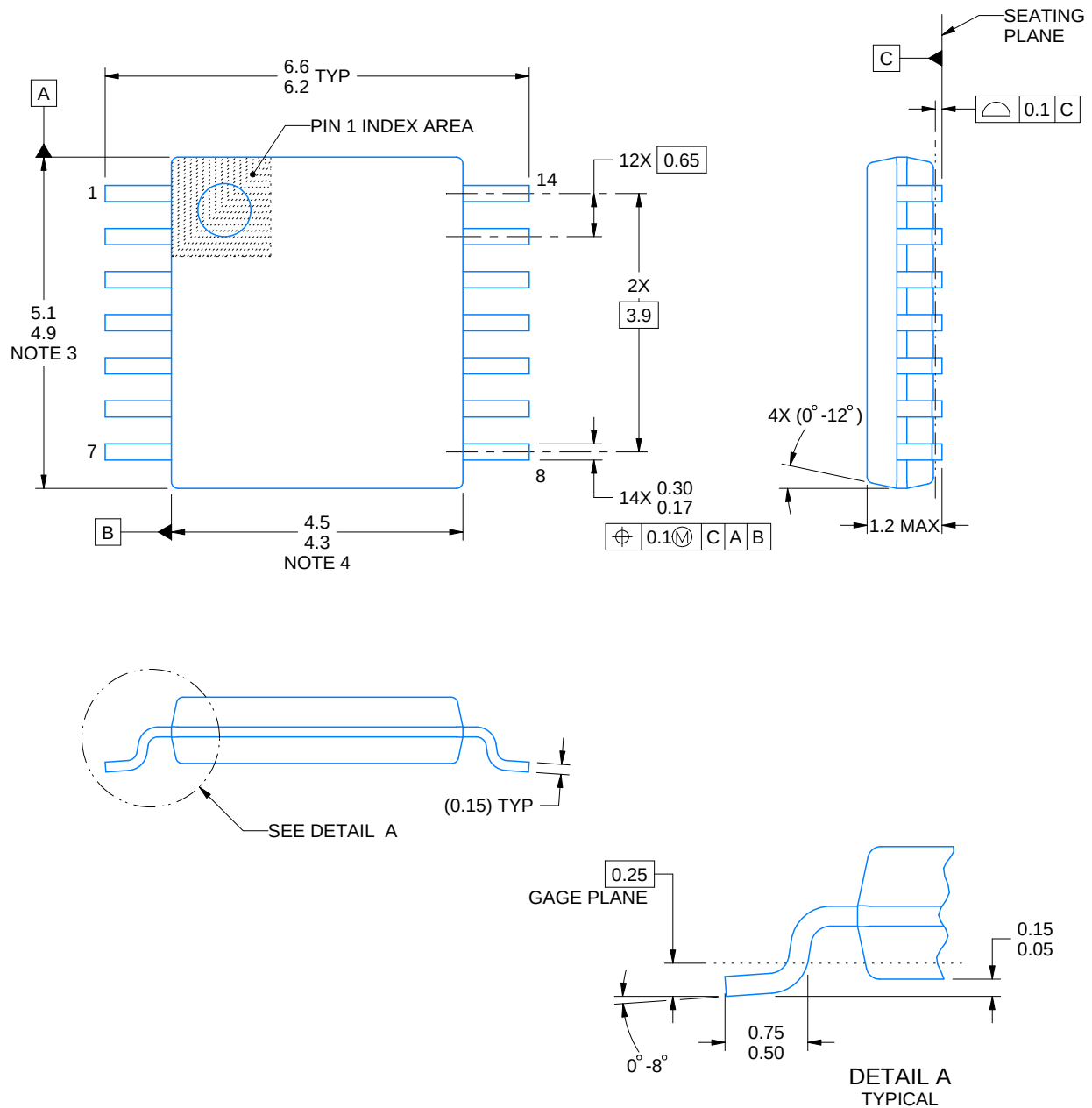
8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

PW0014A

PACKAGE OUTLINE

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



4220202/B 12/2023

NOTES:

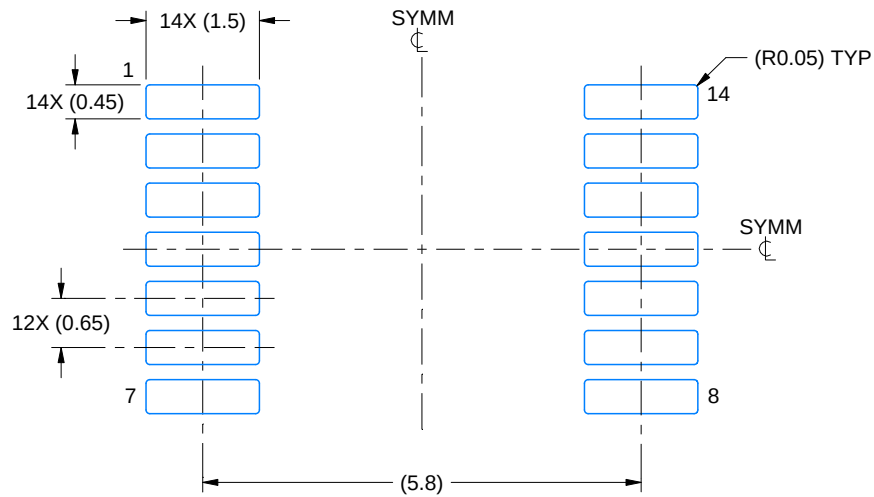
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.

EXAMPLE BOARD LAYOUT

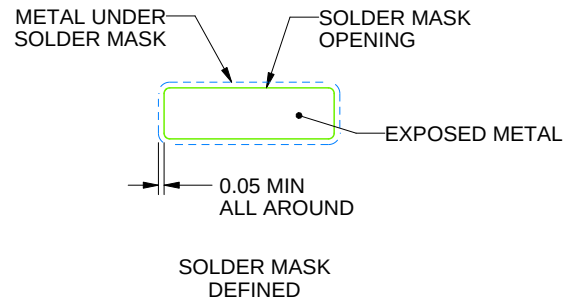
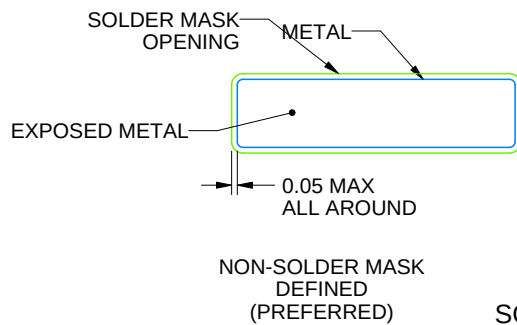
PW0014A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X



SOLDER MASK DETAILS

4220202/B 12/2023

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

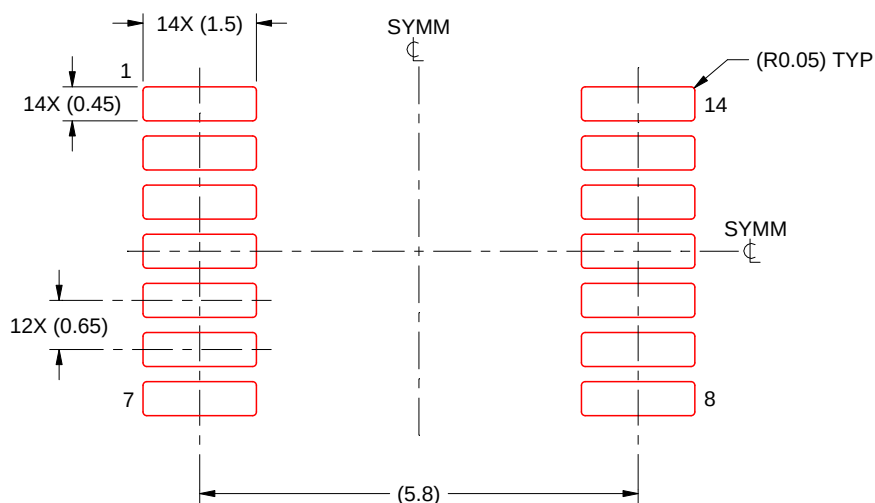
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

PW0014A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4220202/B 12/2023

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

重要なお知らせと免責事項

テキサス・インスツルメンツは、技術データと信頼性データ (データシートを含みます)、設計リソース (リファレンス デザインを含みます)、アプリケーションや設計に関する各種アドバイス、Web ツール、安全性情報、その他のリソースを、欠陥が存在する可能性のある「現状のまま」提供しており、商品性および特定目的に対する適合性の黙示保証、第三者の知的財産権の非侵害保証を含むいかなる保証も、明示的または黙示的にかかわらず拒否します。

これらのリソースは、テキサス・インスツルメンツ製品を使用する設計の経験を積んだ開発者への提供を意図したものです。(1) お客様のアプリケーションに適したテキサス・インスツルメンツ製品の選定、(2) お客様のアプリケーションの設計、検証、試験、(3) お客様のアプリケーションに該当する各種規格や、その他のあらゆる安全性、セキュリティ、規制、または他の要件への確実な適合に関する責任を、お客様のみが単独で負うものとします。

上記の各種リソースは、予告なく変更される可能性があります。これらのリソースは、リソースで説明されているテキサス・インスツルメンツ製品を使用するアプリケーションの開発の目的でのみ、テキサス・インスツルメンツはその使用をお客様に許諾します。これらのリソースに関して、他の目的で複製することや掲載することは禁止されています。テキサス・インスツルメンツや第三者の知的財産権のライセンスが付与されている訳ではありません。お客様は、これらのリソースを自身で使用した結果発生するあらゆる申し立て、損害、費用、損失、責任について、テキサス・インスツルメンツおよびその代理人を完全に補償するものとし、テキサス・インスツルメンツは一切の責任を拒否します。

テキサス・インスツルメンツの製品は、[テキサス・インスツルメンツの販売条件](#)、または [ti.com](https://www.ti.com) やかかるテキサス・インスツルメンツ製品の関連資料などのいずれかを通じて提供する適用可能な条項の下で提供されています。テキサス・インスツルメンツがこれらのリソースを提供することは、適用されるテキサス・インスツルメンツの保証または他の保証の放棄の拡大や変更を意味するものではありません。

お客様がいかなる追加条項または代替条項を提案した場合でも、テキサス・インスツルメンツはそれらに異議を唱え、拒否します。

郵送先住所：Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
Copyright © 2025, Texas Instruments Incorporated